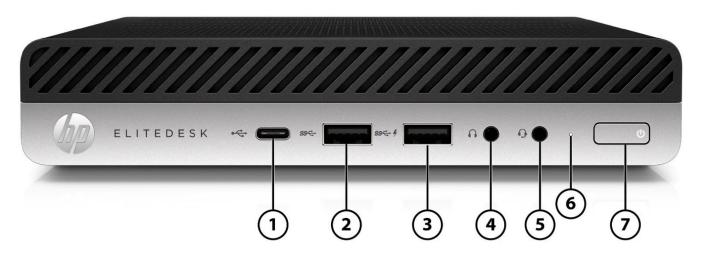
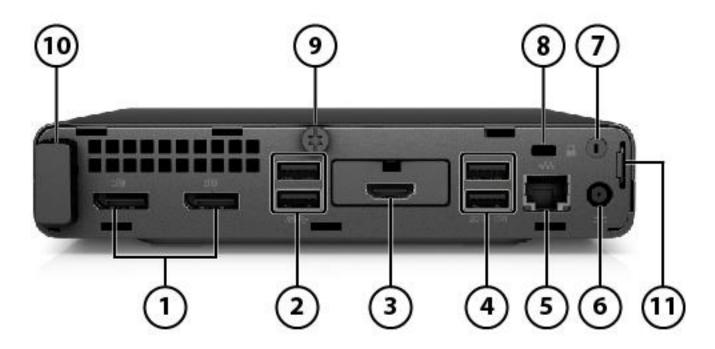
HP EliteDesk 800 G5 Desktop Mini Business PC



- 1. USB Type-C[™] 3.1 Gen 2 port (charge support up to 5V/3A)
- 2. USB 3.1 Gen 2 Type A
- 3. USB 3.1 Gen 1 Type A (charging port)
- 4. Headphone Jack

- 5. Universal Audio Jack with CTIA headset support
- 6. Hard Drive activity light
- 7. Dual-state power button

HP EliteDesk 800 G5 Desktop Mini Business PC



- 1. DisplayPort™ 1.2
- 2. USB 3.1 Gen 2 Type A
- 3. Configurable Option card slot (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, USB Type-C™ with alt mode display, USB Type-C™ with Power Delivery, Discrete Graphics Option Card with DisplayPort™ 1.4, Thunderbolt 3.0, Serial Port, Fiber NIC) (not all options are available on 65W and 95W processors)
- 4. USB 3.1 Gen 1 Type A allows for wake from S4/S5 with keyboard/mouse when connected and enabled in BIOS

- 5. RJ-45 Network connector
- Power connector
- 7. WLAN External Antenna Punchout
- 8. Standard lock slot (10mm)
- 9. Cover Release Thumbscrew
- 10. WLAN Internal Antenna
- 11 Padlock Loop

Not Shown

Slots (1) Internal M.2 2230 connector for WLAN

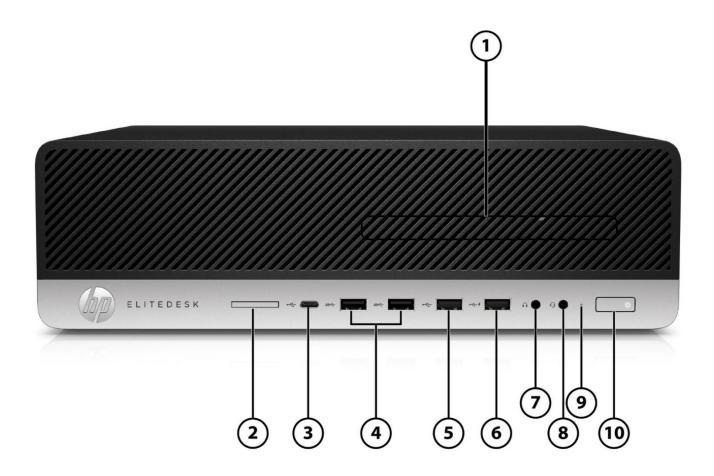
(2) Internal M.2 SSD storage (2230 or 2280 connector)

Bays (1) 2.5- inch SATA drive Bay (not available on 95W processor)

Mounting Support for

- VESA Sleeve Standalone
- Quick Release Bracket
- B300/B500 Mounting bracket
- Integrated Work Center

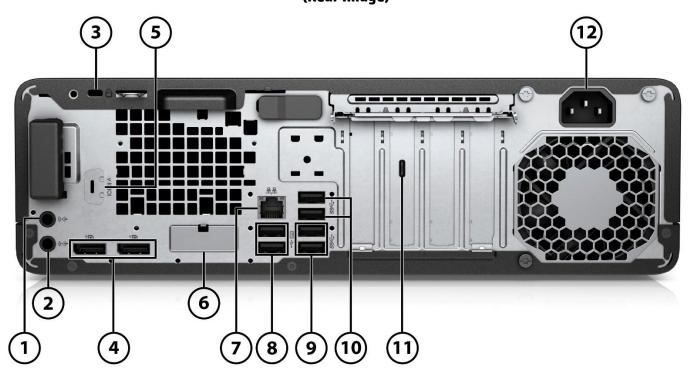
HP EliteDesk 800 G5 Small Form Factor Business PC



- 1. Slim optical drive (optional)
- 2. SD 4 Card Reader (optional)
- 3. USB Type-C[™] port (charge support up to 5V/3A)
- 4. USB 3.1 Gen2 ports (2)
- 5. USB 2.0 port

- 6. USB 2.0 (charge support up to 5V/1.5A)
- 7. Headphone connector
- 8. Universal Audio Jack with CTIA headset support
- 9. Hard drive activity light
- 10. Dual-state power button

HP EliteDesk 800 G5 Small Form Factor Business PC (Rear Image)



- 1. Audio-in connector
- 2. Audio-out connector for powered audio devices
- 3. Standard lock slot
- 4. Dual-Mode DisplayPort™ 1.2 (2)
- 5. Optional serial port shown here not installed
- 6. Optional port (DisplayPort™ 1.2, HDMI 2.0a, VGA or USB-C™) (USB-C™ option has alt mode DisplayPort™ 1.2 or 15W output) shown here not installed
- 7. RJ-45 (network) jack
- 8. USB 2.0 ports with wake from S4/S5 (2)
- 9. USB 3.1 Gen2 ports (2)
- 10. USB 3.1 Gen1 ports (2)
- 11. Optional Thunderbolt PCIe card shown here installed

Not shown

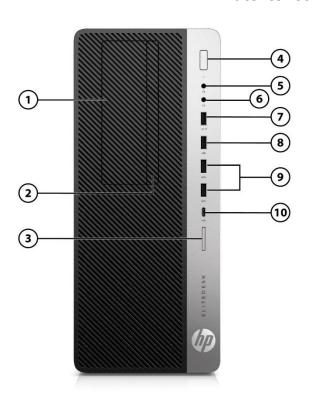
Slots

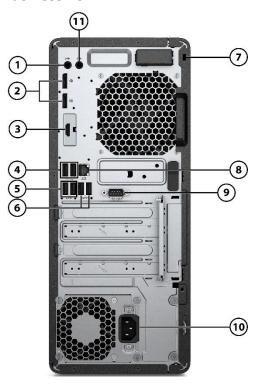
- (2) PCI Express x16 graphics connectors; one wired as an x4
- (2) PCI Express x1
- (2) internal M.2 SSD storage (2230 or 2280 connector)
- (1) internal M.2 WLAN (2230 connector)

Rave

- (1) 2.5" internal storage drive bay
- (2) 3.5" internal storage drive bay (convertible to 2.5")
- (1) 9.5 mm slim optical drive bay

HP EliteDesk 800 G5 Tower Business PC





- 1. 5.25-inch Half-Height Drive Bay (behind bezel)
- 2. Slim optical drive (optional)
- 3. SD 4 Card Reader (optional)
- 4. Dual-state power button
- 5. Universal Audio Jack with CTIA headset support
- 6. Headphone connector
- 7. USB 2.0 port (charge support up to 5V/1.5A)
- 8. USB 2.0 port
- 9. USB 3.1 Gen2 ports (2)
- 10. USB Type-C[™] port (charge support up to 5V/3A)

- 1. Audio-out jack for powered audio devices
- 2. Dual-Mode DisplayPort™ 1.2 (DP++) (2)
- Optional port (DisplayPort™ 1.2, HDMI 2.0a, VGA or USB-C™) (USB-C™ option has alt mode DisplayPort™ 1.2 or 15W output) – Shown here HDMI installed
- 4. USB 2.0 ports with wake from S4/S5 (2)
- 5. USB 3.1 Gen2 ports (2)
- 6. USB 3.1 Gen1 ports (2)
- 7. Standard lock slot
- 8. RJ-45 (network) jack
- 9. Optional serial port shown here installed
- 10. Power cord connector
- 11. Audio-in jack

Not shown

Slots

- (2) PCI Express x16 graphics connectors; one wired as an x4
- (2) PCI Express x1
- (2) internal M.2 SSD storage (2230 or 2280 connector)
- (1) internal M.2 WLAN (2230 connector)

Bays

- (1) 2.5" internal storage drive bay
- (2) 3.5" internal storage drive bay (convertible to 2.5")
- (1) 5.25" half-height drive bay
- (1) 9.5mm slim optical drive bay



HP EliteOne 800 G5 23.8-in All-in-One*



1. Camera (optional)

2. Speakers (optional)

Infrared (IR) and dual facing camera (optional)



- 1. Camera light
- 2. IR camera light
- 3. Full High Definition (FHD) camera
- 4. IR camera
- 5. Rear camera adjustment wheel
- 6. Digital microphones
- 7. Camera light
- 8. FHD camera

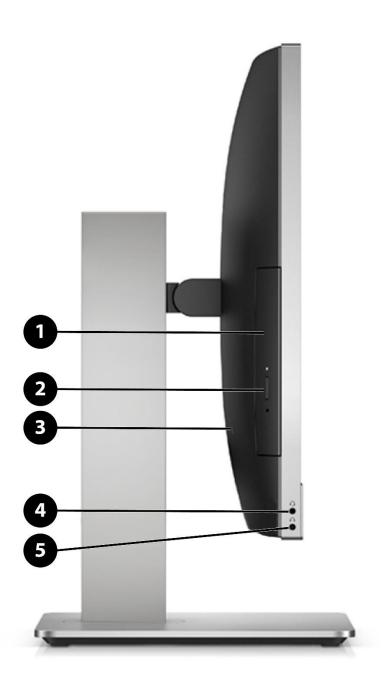
Full High Definition (FHD) camera (optional)



- 1. Camera light
- 2. FHD camera
- 3. Digital microphones

^{*}Available Options: Touch, Non-Touch, HP Sure View, and Discrete Graphics

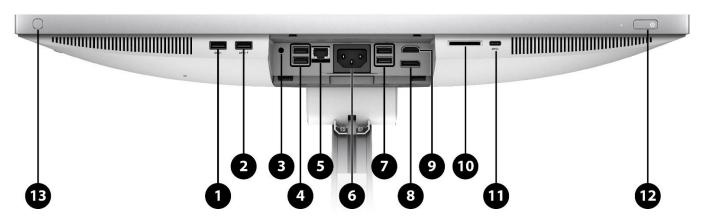
HP EliteOne 800 G5 23.8-in All-in One



- 1. Optical disc drive (optional)
- 2. Optical disc drive eject button (optional)
- 3. Standard lock slot (10 mm)

- 4. Universal Audio Jack with CTIA headset support
- 4. Headphone connector

HP EliteOne 800 G5 23.8-in All-in-One



Bottom components and rear ports (behind security cover)

- 1. USB 3.1 Gen 2 Type-A port
- 2. USB 3.1 Gen 2 Type-A port (charge support up to 5V/1.5A)
- 3. Audio line-out connector
- 4. USB 3.1 Gen 1 Type-A ports (2)
- 5. RJ-45 (network) jack
- 6. Power connector

- 7. USB 3.1 Gen 2 Type-A ports (2) wake capable
- 8. Dual-Mode DisplayPort™1.2 (DP++)
- 9. HDMI 2.0a connector
- 10. SD card reader 4.0 (optional)
- 11. USB 3.1 Type-C™ Gen 2 port (charge support up to 5V/3A)
- 12. Dual-state power button
- 13. Sure View Button (optional)

Not shown

Slots

- (1) internal M.2 PCIe x1 connector for optional wireless NIC
- (2) internal M.2 PCIe x4 connector for optional m.2 SSD

Bays

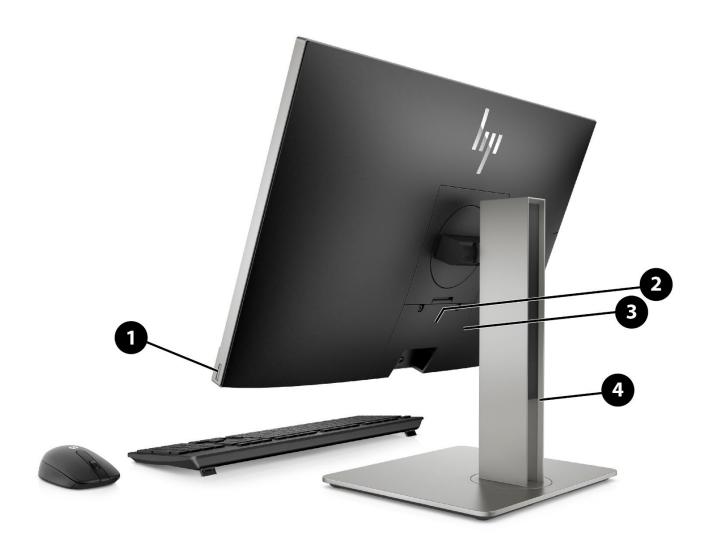
(1) 2.5" internal storage drive bay

VESA

Support for VESA 100 mounting system on back of PC chassis (mounting hardware sold separately)



HP EliteOne 800 G5 23.8-in All-in-One



Rear and side components

- 1. Fingerprint sensor (optional)
- 2. Rear port cover

- 3. Standard lock slot (10 mm)
- 4. Adjustable height stand (optional)

Features

AT A GLANCE

- Choice of four form factors: Tower, Small Form Factor, Desktop Mini and All-In-One (touch/non-touch)
- HP developed and engineered UEFI V2.6 BIOS supporting security, manageability and software image stability
- Intel® Q370 chipset supporting Intel® 9th and select 8th generation Core™ processors, featuring integrated Intel® UHD Graphics and Intel® vPro™ Technology (available with Core i5, Core i7 and Core i9 processors) ^{1,4}
- Processors up to 95W on TWR, SFF and DM
- Intel® Optane™ Memory H10 with Solid State Storage
- Intel® UHD graphics as well as optional discrete graphics configure systems to up to 7 displays (TWR, SFF and DM 35W)²
- Intel® Ethernet Connection I219LM GbE LOM integrated network connection
- Intel® Wi-Fi 6 + BT5 (802.11AX 2x2)
- DDR4 Synchronous Dynamic Random Access Memory (SDRAM) (Transfer rates up to 2666 MT/s)
- Support for up to three monitors via two standard DisplayPort[™] 1.2 connectors and an optional third video port connector which provides the following choices: HDMI 2.0, VGA, DisplayPort[™] 1.2, or USB Type-C[™] with DisplayPort[™] 1.2 for all platforms; USB Type-C[™] with DisplayPort[™] 1.2 and Power Delivery (PD) from Display for 800 G5 DM 35W (see Ports section for port availability by platform). AiO supports up to two additional monitors via DisplayPort[™] or HDMI connectors.²
- Configurable 3rd rear I/O with video port (HDMI 2.0, DisplayPort™ 1.2, VGA, Type-C™ with DisplayPort™ 1.2) or Thunderbolt 3.0 (port on DM, PCIe card on TWR, SFF)
- Configurable AMD® Radeon and NVIDA® GeForce® VR ready discrete graphics on TWR⁵
- Compatibility with HP Mini-In-One 24 Display (800 G5 DM with 100W USB-C +PD option card)
- Models can be configured with multiple data drives in a RAID array
- Skype for Business certified (AiO)
- Audio by Bang & Olufsen (AiO)
- Intel® Unite™ available (AiO, Desktop Mini)
- Intel® Unite™ must be configured at the factory
- EN 60601-1-2: 2015 compliant (AiO)
- Enhanced Security With:

HP Sure Click

HP Sure Start Gen5

HP Sure Run

HP Sure Recover

HP Sure View Gen3 (AiO)

HP Manageability Integration Kit Gen3

HP BIOSphere Gen5

HP Sure Sense

HP Client Security Manager Gen5

Notification with HP Image Assistant Gen3

HP Multi-Factor Authenticate Gen3, features include fingerprint sensor (optional) and IR webcam (optional) both Windows Hello certified (AiO)

- High efficiency energy saving power supply options
- ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country⁶. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/qo/options.
- CCC, CECP and SEPA Certified (TWR/SFF/DM/AiO)
- CECP Certified (AiO)
- TCO Edge for AiO
- PC chassis and all internal components and modules are manufactured with low halogen content³
- Dust filter available for all platforms (except 65W and 95W Desktop Mini, 35W Desktop Mini with Discrete Graphics)
- Protected by HP Services, including limited warranties up to 3-3-3 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Compliance with CE (Class B) / FCC (Class B) / UL (UL609501) / CSA (CSA C22.2 No.60950-1-07) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B)



Features

- 1. Multi core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance
- 2. DisplayPort™ multi-stream monitors 'daisy-chained' together.
- 3. External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.
- 4. Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependant on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with with future "virtual appliances" is yet to be determined."
- 5. VR-ready as optional feature, requires specific configuration to support.
- 6. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

NOTE: See important legal disclosures for all listed specs in their respective features sections

PRODUCT NAME

HP EliteDesk 800 G5 Tower Business PC

HP EliteDesk 800 G5 Small Form Factor Business PC

HP EliteDesk 800 G5 Desktop Mini Business PC

HP EliteOne 800 G5 23.8-inch All-in-One

OPERATING SYSTEM

Preinstalled Windows® 10 Pro 64¹

Windows® 10 Pro 64 (National Academic License)2

Windows® 10 Home 641

Windows® 10 Home Single Language 641

FreeDos

Web-supported only Windows® 10 Enterprise 64¹

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.
- 2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com

CHIPSET

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Q370 PCH-H− vPro™	<u>x</u>	<u>x</u>	<u>x</u>	<u>X</u>



Features

PROCESSORS

Intel® 9 th Generation Core™ Processors	<u>DM</u>	<u>SFF</u>	TWR	<u>AiO</u>
Intel® Core™ i9 9900 Processor with Intel® UHD Graphics 630 (3.1GHz, up to 4.9 GHz with Intel® Turbo Boost,16MB cache, 8 cores) 65W ^{1,2} Supports Intel® vPro™Technology³	х	х	х	х
Intel® Core™ i9 9900K Processor with Intel® UHD Graphics 630 (3.6GHz, up to 5.0 GHz with Intel® Turbo Boost,16MB cache, 8 cores) 95W ^{1,2} Supports Intel® vPro™Technology³	х	х	х	
Intel® Core™ i9 9900T Processor with Intel® UHD Graphics 630 (2.1GHz, up to 4.4 GHz with Intel® Turbo Boost,16MB cache, 8 cores) 35W¹,² Supports Intel® vPro™Technology³	х			
Intel® Core™ i7 9700 processor with Intel® UHD Graphics 630 (3.0 GHz, up to 4.7 GHz with Intel® Turbo Boost, 12 MB cache, 8 cores) 65W ^{1,2} Supports Intel® vPro™Technology³	х	х	х	х
Intel® Core™ i7 9700K Processor with Intel® UHD Graphics 630 (3.6 GHz, up to 4.9 GHz with Intel® Turbo Boost,12MB cache, 8 cores) 95W¹,² Supports Intel® vPro™Technology³	Х	x	х	
Intel® Core™ i7 9700T Processor with Intel® UHD Graphics 630 (2.0Hz, up to 4.3 GHz with Intel® Turbo Boost,12MB cache, 8 cores) 35W¹,² Supports Intel® vPro™Technology³	х			
Intel® Core™ i5 9600 processor with Intel® UHD Graphics 630 (3.1 GHz, up to 4.8 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) ^{1, 2} Supports Intel® vPro™Technology³	х	х	х	x
Intel® Core™ i5 9600K processor with Intel® UHD Graphics 630 630 (3.7 GHz, up to 4.6 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) 95W ^{1, 2} Supports Intel® vPro™Technology³	х	х	х	
Intel® Core™ i5 9600T processor with Intel® UHD Graphics 630 (2.3 GHz, up to 3.9 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) ^{1, 2} Supports Intel® vPro™Technology³	х			
Intel® Core™ i5 9500 processor with Intel® UHD Graphics 630 (3.0 GHz, up to 4.1 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) ^{1, 2} Supports Intel® vPro™Technology³	х	х	х	x
Intel® Core™ i5 9500T processor with Intel® UHD Graphics 630 (2.2 GHz, up to 3.7 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) ^{1, 2} Supports Intel® vPro™Technology³	х			
Intel® Core™ i5 9400 processor with Intel® UHD Graphics 630 (2.9 GHz, up to 4.1 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores)	Х	х	Х	Х
Intel® Core™ i5 9400T processor with Intel® UHD Graphics 630 (1.8 GHz, up to 3.4 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores)	Х			
Intel® Core™ i5 8400 processor with Intel® UHD Graphics 630 (2.8 GHz, up to 4.0 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores)	Х	Х	Х	Х
Intel® Core™ i5 8400T processor with Intel® UHD Graphics 630 (1.7 GHz, up to 3.3 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores)	X			
Intel® Core™ i3 9300 processor with Intel® UHD Graphics 630 (3.7 GHz, 8 MB cache, 4 cores)¹	х	х	х	х
Intel® Core™ i3 9300T processor with Intel® UHD Graphics 630 (3.2 GHz, 8 MB cache, 4 cores)¹	х			



Intel® Core™ i3 9100 processor with Intel® UHD Graphics 630 (3.6 GHz, 6 MB cache, 4 cores)¹	X	X	Х	Х
Intel® Core™ i3 9100T processor with Intel® UHD Graphics 630 (3.1 GHz, 6 MB cache, 4 cores)¹	х			

Intel® 8 th Generation Core™ Processors	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Core™ i7 8700 processor with Intel® UHD Graphics 630 (3.2 GHz, up to 4.6 GHz with Intel® Turbo Boost, 12 MB cache, 6 cores) ^{1, 2} Supports Intel® vPro™Technology³	X	х	x	х
Intel® Core™ i7 8700T processor with Intel® UHD Graphics 630 (2.4 GHz, up to 4.0 GHz with Intel® Turbo Boost, 12 MB cache, 6 cores) ^{1, 2} Supports Intel® vPro™Technology³	X			
Intel® Core™ i5 8500 processor with Intel® UHD Graphics 630 (3.0 GHz, up to 4.1 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) ^{1,2} Supports Intel® vPro™Technology³	X	х	x	х
Intel® Core™ i5 8500T processor with Intel® UHD Graphics 630 (2.1 GHz, up to 3.5 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) ^{1,2} Supports Intel® vPro™Technology³	X			
Intel® Core™ i3 8100 processor with Intel® UHD Graphics 630 (3.6 GHz, 6 MB cache, 4 cores)¹	Х	Х	Х	X
Intel® Core™ i3 8100T processor with Intel® UHD Graphics 630 (3.61GHz, 6 MB cache, 4 cores)¹	Х			

Intel® Pentium® Processors	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Pentium® Gold G5420 processor with Intel® UHD Graphics 610 (3.8 GHz, 4 MB cache, 2 cores)¹	Х	х	х	х
Intel® Pentium® Gold G5420T processor with Intel® UHD Graphics 610 (3.2 GHz, 4 MB cache, 2 cores)¹	х			
Intel® Pentium® Gold G5600 processor with Intel® UHD Graphics 630 (3.9 GHz, 4 MB cache, 2 cores)¹	Х	х	х	х
Intel® Pentium® Gold G5600T processor with Intel® UHD Graphics 630 (3.3GHz, 4 MB cache, 2 cores)¹	х			
Intel® Pentium® Gold G5620 processor with Intel® UHD Graphics 630 (4.0 GHz, 4 MB cache, 2 cores)¹	х	Х	Х	х

Intel® Celeron™ Processors	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Celeron® G4930 processor with Intel® UHD Graphics 610 (3.2 GHz, 2 MB cache, 2 cores)¹	х	Х	Х	Х
Intel® Celeron® G4930T processor with Intel® UHD Graphics 610 (3.0 GHz, 2 MB cache, 2 cores)¹	х			

^{1:} Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

^{3.} Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependant on 3rd party



^{2.} Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

Features

software providers. Compatibility of this generation of Intel vPro technology-based hardware with with future "virtual appliances" is yet to be determined.

GRAPHICS

Integrated Intel® Graphics	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u> AiO</u>
Intel® UHD Graphics 630 (integrated on 9th gen Core i9/i7/i5/i3, Pentium® Gold G5600, G5500)	X	X	Х	X
Intel® UHD Graphics 610 (integrated on 9 th gen Pentium® Gold G5400, Celeron® G4900)	х	X	х	х

tional Discrete Graphics Solutions	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
NVIDIA® GeForce® RTX 2080 8GB FH 3DP HDMI Graphics Card*			X	
NVIDIA® GeForce® RTX 2070 8GB FH 3DP HDMI Graphics Card*			X	
NVIDIA® GeForce® RTX 2070 Super 8GB Graphics Card			X	
NVIDIA® GeForce® RTX 2060 6GB FH Graphics Card*			X	
NVIDIA Quadro P1000 4GB Graphics Card			X	
NVIDIA® Quadro P620 2GB Graphics Card		Х	X	
NVIDIA® Quadro P400 2GB Graphics Card		Х	X	
NVIDIA® GeForce® GT 730 2GB DP DVI Graphics Card		X	X	
AMD® Radeon™ RX 580 8GB FH 3DP 1HDMI Graphics Card*			X	
AMD® Radeon™ RX 560X 4GB GDDR5**	Х			Х
AMD® Radeon™ RX 550 4GB 1DP 1HDMI Graphics Card		Х	X	
AMD® Radeon™ R7 430 2GB GDDR5 64bit DP+VGA***		X	X	
AMD® Radeon™ R7 430 2GB GDDR5 64bit 2DP		X	X	
AMD® Radeon™ 520 1GB VGA +DP			Х	

^{*}Requires 500W chassis

NOTE: As of 2019, AMD Radeon™ RX 560 is renamed to AMD Radeon™ RX 560X

dapters and Cables	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP DisplayPort™ Cable	Х	X	X	Х
HP DisplayPort™ to DVI-D Adapter	Х	X	Х	Х
HP DisplayPort™ to HDMI 4K Adapter	Х	X	Х	Х
HP DisplayPort™ to VGA Adapter	Х	X	X	Х
HP USB-C™ to USB 3.0	X	X	Х	Х
HP USB to Serial Port Adapter	X	X	Х	Х
HP USB-C™ to HDMI 4K Adapter	Х			
HP DisplayPort to HDMI True 4K Adapter				Х
HP DVI Cable				Х
HP HDMI Standard Cable Kit (HDMI)				Х
HP DVI Cable Kit				Х



^{**}Only available on the Touch Version All-in-One

^{***}Not available in all regions

HP HDMI to VGA Adapter		X
HP UHD USB Graphics Adapter		Х



Features

STORAGE

3.5 inch SATA Hard Disk Drives (HDD)	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
500GB 7200RPM 3.5in SATA HDD		X	X	
1TB 7200RPM 3.5in SATA HDD		X	X	
2TB 7200RPM 3.5in SATA HDD		Х	Х	

2.5 inch SATA Hard Disk Drives (HDD)	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
500GB 7200RPM 2.5in SATA HDD	X	X	X	X
1TB 7200RPM 2.5in SATA HDD	X	X	X	X
2TB 5400RPM 2.5in SATA HDD	X	X	X	X
500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD*	X	X	X	X
500GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD*	Х	Х	Х	Х

NOTE*: Storage Drivelock does not work with Self Encrypting or Optane based storage.

2.5 inch Solid State Drives (SSD)	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u> AiO</u>
256GB 2.5in SATA Three Layer Cell SSD	X	X	Х	X
512GB 2.5in SATA Three Layer Cell SSD	X	X	X	X
256GB 2.5in SATA Self Encrypted OPAL2 Three Layer Cell SSD*	X	X	Х	X
512GB 2.5in SATA Self Encrypted OPAL2 Three Layer Cell SSD*	X	X	X	X
256GB 2.5in SATA Self Encrypted Federal Information Processing Standard SSD*	Х	Х	X	Х
512GB 2.5in SATA Self Encrypted Federal Information Processing Standard SSD*	X	X	X	Х

NOTE*: Storage Drivelock does not work with Self Encrypting or Optane based storage.

I.2 PCIe NMVe Solid State Drives (SSD)	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u> AiO</u>
256GB M.2 2280 PCIe NVMe SSD	X	X	X	X
512GB M.2 2280 PCIe NVMe SSD	Х	Х	X	Х
1TB M.2 2280 PCIe NVMe SSD		X	X	
128GB M.2 2280 PCIe NVMe Three Layer Cell SSD	Х	Х	X	X
256GB M.2 2280 PCIe NVMe Three Layer Cell SSD	Х	X	X	X
512GB M.2 2280 PCIe NVMe Three Layer Cell SSD	Х	Х	X	X
1TB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
2TB M.2 2280 PCIe NVMe Three Layer Cell SSD	Х	Х	X	X
256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD*	X	X	X	X
512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD*	Х	Х	X	X
256GB Intel® Optane™ Memory H10 with Solid State Storage*	X	X	X	X
512GB Intel® Optane™ Memory H10 with Solid State Storage*	X	Х	X	X

NOTE*: Storage Drivelock does not work with Self Encrypting or Optane based storage.





Optical Disc Drives	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP 9.5mm Slim DVD-ROM Drive		Х	X	Х
HP 9.5mm Slim DVD Writer Drive		Х	Х	X
HP 9.5mm Slim Blu-Ray Writer Drive		Х	X	X

Rem	ovable	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u> AiO</u>
	SSD 256GB M.2 PCIe NVMe TLC Removable			X	
	SSD 512GB M.2 PCIe NVMe TLC Removable			X	
	SSD 1TB M.2 PCIe NVMe TLC Removable			X	

Media Card Reader	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	
SD 4.0 with 5-in-1 Interface (Supports SD, SDXC, SDHC, UHS-I, UHS-II)		Х	Х	X	Ī

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

MEMORY

Memory Type	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
DDR4-2666 (Transfer rates up to 2666 MT/s), 64 GB, 2 SODIMM	X			X
DDR4-2666 (Transfer rates up to 2666 MT/s), 128 GB, 4 DIMM		Х	Х	

Memory Configuration	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
4 GB (1 x 4 GB)	X	X	Х	Х
8 GB (2 x 4 GB)	X	X	Х	Х
8 GB (1 x 8 GB)	X	X	Х	Х
16 GB (2 x 8 GB)	X	X	Х	X
16 GB (1 x 16 GB)	X	X	Х	Х
32 GB (2 x 16 GB)	X	X	Х	X
32 GB (4 x 8 GB)		X	Х	
32 GB (1 x 32 GB)	X	X	Х	X
64 GB (4 x 16 GB)		X	Х	
64 GB (2 x 32 GB)	X	Х	Х	X
128 GB (4 x 32 GB)		X	Х	

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.

Memory modules support data transfer rates up to 2666 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

NOTE: All memory slots are customer accessible / upgradeable.





NETWORKING/COMMUNICATIONS

Ethe	net (RJ-45)	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
	Intel® I219-LM Gigabit Network Connection LOM (standard)	X	X	X	X
	Intel® Ethernet I210-T1 PCIe x1 Gb Network Interface Card (optional)		Х	Х	

less¹	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Wi-Fi 6 AX200 + BT5 (802.11AX 2x2 vPro, supporting gigabit file transfer speed)	х	Х	Х	Х
Intel® Wi-Fi 6 AX200 + BT5 (802.11AX 2x2 non-vPro, supporting gigabit file transfer speed)	х	Х	Х	х
Intel Wireless-AC 9560 802.11ac 2x2 Wi-Fi + BT5 (vPro, supporting gigabit file transfer speeds)	х	Х	Х	х
Intel Wireless-AC 9560 802.11ac 2x2 Wi-Fi + BT5 (non-vPro, supporting gigabit file transfer speeds)	х	Х	Х	х
Realtek RTL8822BE 802.11ac 2x2 Wi-Fi + BT4.2		X	X	Х
Realtek RTL8821CE 802.11ac 1x1 Wi-Fi + BT4.2				Х

^{1.} Wireless access point and Internet service required and not included. Availability of public wireless access points limited. The specifications for the 802.11ax WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the PC to communicate with 802.11ax WLAN devices. Wi-Fi 6 requires a wireless router, sold separately, that supports 802.11ax (Wi-Fi 6). Only available in countries where 802.11ax is supported.

KEYBOARDS AND POINTING DEVICES

Keyboards	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP USB Premium Keyboard	X	Х	Х	X
HP USB Conferencing Keyboard	X	Х	Х	X
HP Wireless Collaboration Keyboard	X	Х	Х	Х
HP USB Collaboration Keyboard	X	Х	Х	X
HP USB and PS/2 Washable Keyboard ¹	X	Х	Х	X
HP USB Smart Card (CCID) Keyboard	X	Х	X	X
HP USB Business Slim Keyboard	X	Х	Х	X
HP USB Keyboard	X	Х	X	X
HP PS/2 Business Slim Keyboard ¹		Х	Х	
HP Wireless Business Slim Keyboard and Mouse	X	Х	Х	X
HP USB Business Slim Antimicrobial Keyboard ²	X	Х	Х	Х

se	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP PS/2 Mouse ¹		X	Х	
HP USB Optical Mouse	Х	X	Х	X
HP USB Premium Mouse	X	X	Х	X
HP USB 1000dpi Laser Mouse	Х	X	Х	X
HP USB and PS/2 Washable Mouse ¹	X	X	X	X
Antimicrobial USB Mouse ²	Х	Х	Х	Х





HP USB Hardened Mouse ²	X	X	X	X
HP USB Fingerprint Reader Mouse		X	X	Х
HP USB Grey Mouse ²	Х	Х	Х	Х

^{1.} PS/2 port not available on EliteOne 800 G5 AiOs and not available on any EliteDesk 800 G5 DMs

SECURITY

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
TPM 2.0 (FW: 7.85) endpoint security controller (Infineon SLB9670) shipped with Windows 10. Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.	х	х	х	x
Solenoid Lock & Intrusion Sensor		X	Х	
Intrusion Sensor for DM/AiO (integrated in the PCA, can be enabled/disabled through BIOS)	X			х
Support for chassis cable lock devices	X (10 mm or smaller)	x	х	х
Support for chassis padlocks devices	Х	Х	X	
HP Fingerprint Sensor (standard on 800 G5 AiO touch models and optional on non-touch models)				х
SATA port disablement (via BIOS)	Х	Х	Х	Х
Serial, USB enable/disable (via BIOS)	Х	X	X	X
Intel® Identify Protection Technology (IPT) ¹	X	Х	Х	X
Serial, parallel, USB enable/disable (via BIOS)	Х	X	X	X
Optional USB Port Disable at factory (user configurable via BIOS)	Х	Х	X	X
Removable media write/boot control	Х	Х	X	X
Power-on password (via BIOS)	X	X	X	X
Setup password (via BIOS)	Х	X	X	X

^{1.} Models configured with Intel® Core™ processors have the ability to utilize advanced security protection for online transactions. IPT, used in conjunction with participating web sites, provides double identity authentication by adding a hardware component in addition to the usual user name and password. IPT is initialized through an HP Client Security module.



^{2.} Not available in all regions

Features

PORTS

orts – Standard	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
USB 2.0	N/A	2 including 1 fast charging (front); 2 including wake from S4/S5 (rear)	2 including 1 fast charging (front); 2 including wake from S4/S5 (rear)	N/A
USB 3.1 Gen 1	1 front, 2 rear	2 rear	2 rear	2 rear
USB 3.1 Gen 2	1 front, 2 rear	2 front; 2 rear	2 front; 2 rear	4 rear
USB Type-C™ 3.1 Gen 2 (15W)	1 front; 1 rear (option)	1 front; 1 rear (option)	1 front; 1 rear (option)	1 rear
Video	2 DisplayPort™ 1.2 (rear) 1 Configurable video port (rear) (Choice of DisplayPort™ 1.2, HDMI™ 2.0a, VGA, or USB Type-C™ with alt mode display port and power delivery) For models with discrete graphics: 1 DisplayPort™ 1.4 (rear)	2 DisplayPort™ 1.2 (rear) 1 Configurable video port (rear) (Choice of DisplayPort™ 1.2, HDMI™ 2.0a, VGA, or USB Type-C™ with alt mode display or 15W output)	2 DisplayPort™ 1.2 (rear) 1 Configurable video port (rear) (Choice of DisplayPort™ 1.2, HDMI™ 2.0a, VGA, or USB Type-C™ with alt mode display port or 15W output)	For models with integrated graphics: 1 DisplayPort™ 1.2 (rear) 1 HDMI™ 2.0a (rear) For models with discrete graphics 1 DisplayPort™ 1.4 (rear) 1 HDMI™ 2.0a (rear)
Audio	1 Headphone (front), 1 Universal Audio Jack with CTIA headset support (front))	1 Headphone (front), 1 Universal Audio Jack with CTIA headset support (front)); 1 Audio-out (rear), 1 Audio-in (rear)	1 Headphone (front), 1 Universal Audio Jack with CTIA headset support (front)); 1 Audio-out (rear), 1 Audio-in (rear)	1 Line out (rear) 1 CTIA UAJ (side) 1Audio out (side)
Network Interface	RJ45	RJ45	RJ45	RJ45

I/O Ports – Optional	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Serial (RS-232)	1 (rear)(option)	1 (rear) (option)	1 (rear) (option)	N/A
Serial (RS-232) and PS/2 combination	N/A	1 (rear) (option)	1 (rear) (option)	N/A

Features

I/O P	orts – Internal Ports	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
	Internal SATA storage connector(s)	N/A	3	4	2
	Internal SATA storage connector (Data and Power)	1	N/A	N/A	N/A

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

lots	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
M.2 PCIe	(1) M.2 PCle x1 2230 (for WLAN) (2) M.2 PCle x4 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage)
PCI Express v3.0 x1	N/A	2	2	N/A
PCI Express v3.0 x16 (wired as x4)	N/A	1	1	N/A
PCI Express v3.0 x16	N/A	1	1	N/A

NOTE: The TWR can support a single graphics card up to 75W. When configured with dual graphics cards support is limited to 35W for each.

Bays	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
5.25" Half Height (External)	N/A	N/A	1	N/A
9mm Slim Optical Disc Drive (ODD)	N/A	1	1	1
SD Card Reader	N/A	1	1	1
2.5" Internal Storage Drive	1	1	1	1
3.5" Internal Storage Drive	N/A	2	2	N/A

SATA 2.5" internal storage drive cannot be selected if 2nd M.2, discrete graphic card, or 95W processor is selected.



SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS

HP BIOSphere Gen5 ¹⁷
HP DriveLock & Automatic DriveLock²⁰
BIOS Update via Network
Master Boot Record Security
Power On Authentication
HP Secure Erase ¹⁸
Absolute Persistence Module ¹⁹
RAID Configurations³³
Pre-boot Authentication
HP Wireless Wakeup

Software

HP Native Miracast Support ¹⁵
HP Hotkey Support - CMIT
HP Recovery Manager
HP JumpStarts
HP Privacy Settings
HP Setup Integrated OOBE
HP Support Assistant ²¹
HP Noise Cancellation Software
HP PC Hardware Diagnostics Windows
Buy Office (sold separately)
Intel® Unite (optional for AiOs and DMs)
HP Sure View Gen3 (AiO)

Manageability Features

HP Driver Packs ²²
HP System Software Manager (SSM)
HP BIOS Config Utility (BCU)
HP Client Catalog
HP Image Assistant Gen4
HP Manageability Integration Kit Gen3 ²³
Ivanti Management Suite ²⁴
HP Cloud Recovery³⁹

Client Security Software

HP Client Security Suite Gen5 ²⁵ including:
HP Security Manager ²⁶ (including Credential Manager, HP Password Manager, HP Spare Key)
HP Fingerprint Sensor ³¹
HP Device Access Manager
HP Power On Authentication
HP Sure Sense
Windows Defender ²⁷



Features

Security Management

HP Secure Erase¹⁸

TPM 2.0 (FW: 7.85) endpoint security controller (Infineon SLB9670) shipped with Windows 10. Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.

SATA 0,1 port disablement (viaBIOS)

RAID configurations³³

Serial, USB enable/disable (viaBIOS)

Power-on password (viaBIOS)

Setup password (viaBIOS)

Support for chassis padlocks and cable lock devices

Integrated hood sensor

HP Sure Click Gen238

HP Sure Start Gen5³⁰

HP Sure Run³⁵

HP Sure Recover³⁶

- 15. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming
- 17. HP BIOSphere Gen5 requires Intel® or AMD® 9th Gen processors. Features may vary depending on the platform and configurations.
- 18. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88. Supported on Elite platforms with BIOS version F.03 or higher.
- 19. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use

the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

- 20. Storage Drivelock does not work with Self Encrypting or Optane based storage.
- 21. HP Support Assistant requires Windows and Internet access.
- 22. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 23. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- 24. Ivanti Management Suite subscription required.
- 25. HP Client Security Manager Gen5 requires Windows and is available on select HP Pro and Elite PCs. See product specifications for details.
- 26. HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
- 27. Windows Defender Opt in Windows 10 and internet connection required for updates.
- 30. HP Sure Start Gen5 is available on select HP PCs with Intel processors. See product specifications for availability.
- 31. HP Fingerprint Sensor available on 800 G5 AiO touch models and optional on 800 G5 AiO non-touch models
- 33. RAID configuration is optional and requires two equivalent hard drives.
- 34. RAID 1 is pre-installed and functionality will require a second hard drive.
- 35. HP Sure Run is available on HP Elite products equipped with 8th and 9th generation Intel® or AMD® processors.
- 36. HP Sure Recover is available on HP Elite PCs with 8th generation Intel® or AMD® processors and requires an open, wired network connection. Not available on platforms with multiple internal storage drives, Intel® Optane™. You must back up important files, data, photos, videos, etc. before use to avoid loss of data.
- 38. HP Sure Click is available on most HP PCs and supports Microsoft® Internet Explorer, Google Chrome, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
- 39. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630.



ENVIRONMENTAL & INDUSTRY

ENERGY STAR® certified models available

EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country¹. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options.

Low halogen (chassis, all internal components and modules)² TAA compliant models available

1. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information 2. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 50° to 95° F (10° to 35° C)¹

Non-operating: -22° to 140° F (-30° to 60° C)

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 5% to 95% (non-condensing at ambient)

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50000ft (15240 m)

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.





HP EliteDesk 800 Desktop Mini G5 series

Eco-Label Certifications & declarations	This product has received or is in the be labeled with one or more of these. IT ECO declaration US ENERGY STAR® EPEAT® 2019 registered where apphttp://www.epeat.net for registration party option store for solar generate. *Based on US EPEAT® registration accordance.	e marks: olicable. EPEAT ® on status by coun or accessories at ding to IEEE 1680.1 nation.	registration varie try. Search keywo http://www.hp.co -2018 EPEAT®. Sta	es by country. See ord generator on HP's 3rd om/go/options. tus varies by country. Visit	
System Configuration	The configuration used for the Energy			e Emissions data for the	
Energy Consumption (in accordance with US ENERGY STAR® test method)	Desktop model is based on a "Typica" 115VAC, 60Hz	230VAC		100VAC, 50Hz	
Normal Operation (Short idle)	13.27 W	13.51	ı W	13.11 W	
Normal Operation (Long idle)	13.11 W	13.27	7 W	12.88 W	
Sleep	0.75 W	0.81	W	0.75 W	
Off	0.69 W	0.74	W	0.68 W	
Heat Dissipation* Normal Operation	efficiency data listed is for a typically power supply, and a Microsoft Windo	ows® operating s 230VAC	ystem. , 50Hz	100VAC, 50Hz	
(Short idle)	45 BTU/hr	46 BTI	J/hr	45 BTU/hr	
Normal Operation (Long idle)	45 BTU/hr	45 BTI		44 BTU/hr	
Sleep	3 BTU/hr	3 BTU		3 BTU/hr	
Off	2 BTU/hr	3 BTU	•	2 BTU/hr	
	NOTE: Heat dissipation is calculated attained for one hour.	based on the me	asured watts, ass	suming the service level is	
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)			ound Pressure L _{pAm} , decibels)	
Typically Configured – Idle	3			20	
Fixed Disk – Random writes	3.9			22	
ongevity and Upgrading.	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years after the end oproduction.				
			ve 2006/66/EC		





	Battery size: CR2032 (coin cell)				
	Battery type: Lithium				
Additional Information	This produce	t is in compliance with the Restrictions of Hazardous Subs	tances (RoHS) directive -		
	2011/65/EC.				
	• This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE)				
	Directive – 20		5 lif		
		t is in compliance with California Proposition 65 (State of C	California; Safe Drinking		
		oxic Enforcement Act of 1986).	1 11		
		t is in compliance with the IEEE 1680 (EPEAT) standard, se			
		status by country. Search keyword generator on HP's 3rd p	party option store for solar		
		cessories at http://www.hp.com/go/options	1 15044450 11504640		
		ts weighing over 25 grams used in the product are marked	per ISO11469 and ISO1043.		
		ct contains 0% post-consumer recycled plastic (by wt.)	. cre.		
	•	t is 95.1% recycle-able when properly disposed of at end			
Packaging Materials	External:	PAPER/Corrugated	322 g		
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	33 g		
		PLASTIC/Polyethylene low density	5 g		
Material Usage		does not contain any of the following substances in excess	s of regulatory limits (refer		
		neral Specification for the Environment at			
		np.com/hpinfo/globalcitizenship/environment/pdf/gse.pd	f):		
	 Asbestos 				
	• Certain Azo				
		minated Flame Retardants – may not be used as flame ret	ardants in plastics		
	• Cadmium				
		Hydrocarbons			
	• Chlorinated				
	Formaldehy				
		d Diphenyl Methanes			
		nates and sulfates			
		ead compounds			
		kide Batteries	- h - fua auth h - u dh - d - u		
		ishes must not be used on the external surface designed to	be frequently fiantited of		
	carried by the	e user. eting Substances			
		iated Biphenyls (PBBs)			
		lated Biphenyl Ethers (PBBEs)			
		rated Biphenyl Oxides (PBBOs)			
		ated Biphenyl (PCB)			
		ated Diprienyl (PCB) ated Terphenyls (PCT)			
		ated Terphenyls (PCT) hloride (PVC) – except for wires and cables, and certain ret	ail nackaging has boon		
		emoved from most applications.	ait packayiiiy iids Deeli		
	Radioactive				
		: Substances (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)			
	* IIIDULYL IIII	(1617, Implienty, IIII (1717, Impuly), IIII Oxide (1610)			



Features

Packaging Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP EliteDesk 800 Small Form Factor G5 series

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®



net for registration	cable. EPEAT ® registration varie status by country. Search keyw accessories at http://www.hp.co	ord generator on HP's 3rd			
*Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.					
	Consumption and Declared Noise Configured Desktop.	se Emissions data for the			
60Hz	230VAC, 50Hz	100VAC, 50Hz			
W	10.98 W	10.905 W			
W	10.063 W	9.988 W			
W	1.388 W	1.173 W			
W	0.599 W	0.601 W			
computers marked w vironmental Protecti odel family does not ted is for a typically c	or an ENERGY STAR® compliant with the ENERGY STAR® Logo are on Agency (EPA) ENERGY STAR® offer ENERGY STAR® compliant configured PC featuring a hard d is® operating system.	compliant with the specifications for configurations, then energy			
60Hz	230VAC, 50Hz	100VAC, 50Hz			
3TU/hr	15.6294 BTU/hr	15.0138 BTU/hr			
BTU/hr	14.364 BTU/hr	13.5432 BTU/hr			
TU/hr	1.4364 BTU/hr	1.2996 BTU/hr			
ΓU/hr	1.2996 BTU/hr	1.1628 BTU/hr			
ation is calculated ba our.	ased on the measured watts, as	suming the service level is			
Sound Power (L _{WAd} , bels)	_	ound Pressure L _{pAm} , decibels)			
3.2		23			
3.6		25			
This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.					
thic product complex	with EU Directive 2006/66/50				
the product do not co ne1ppm by weight	ntain:				
t	the product do not co he1ppm by weight	than 20ppm by weight 032 (coin cell)			





Additional Information	This produce	t is in compliance with the Restrictions of Hazardon	us Substances (RoHS) directive -			
	2011/65/EC.					
	 This HP product is designed to comply with the Waste Electrical and Electronic Equipment Directive – 2002/96/EC. 					
	 This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard, see http://www.epeat.ne 					
		status by country. Search keyword generator on HP	's 3rd party option store for solar			
		cessories at http://www.hp.com/go/options				
		rts weighing over 25 grams used in the product are				
		ct contains 0% post-consumer recycled plastic (by v				
Daalia sina Mataviala		ct is 95.1% recycle-able when properly disposed of				
Packaging Materials	External:	PAPER/Corrugated	1158 g			
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	320 g			
		PLASTIC/Polyethylene low density	28 g			
Material Usage	to the HP Gei	does not contain any of the following substances in neral Specification for the Environment at	-			
		hp.com/hpinfo/globalcitizenship/environment/pdf,	/gse.pdf):			
	 Asbestos 					
	Certain Azo					
		minated Flame Retardants – may not be used as fla	ame retardants in plastics			
	• Cadmium	I I I I I I I I I I I I I I I I I I I				
	Chlorinated Hydrocarbons Chlorinated Paraffins					
	• Formaldeh					
		ed Diphenyl Methanes				
		nates and sulfates				
		ead compounds				
		kide Batteries				
		ishes must not be used on the external surface desi	ianed to be frequently handled or			
	carried by th					
		leting Substances				
		nated Biphenyls (PBBs)				
		nated Biphenyl Ethers (PBBEs)				
	_	nated Biphenyl Oxides (PBBOs)				
		ated Biphenyl (PCB)				
		ated Terphenyls (PCT)				
		hloride (PVC) – except for wires and cables, and cer	tain retail packaging has been			
	_	emoved from most applications.				
	Radioactive Tributyl Tin	e Substances 1 (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTC	1)			
Packaging Usage		nese guidelines to decrease the environmental impa				
-		he use of heavy metals such as lead, chromium, me				
	materials.	ne ase of neavy metals such as lead, emormali, me	reary and cadman in packaging			
	• Eliminate tl	he use of ozone-depleting substances (ODS) in pack	kaging materials.			
		kaging materials for ease of disassembly.				
		he use of post-consumer recycled content material	s in nackaging materials			
		recyclable packaging materials such as paper and (, , ,			
		e and weight of packages to improve transportation				
	• Plastic paci	kaging materials are marked according to ISO 1146	y and Din o i 20 Standards.			

Features

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf





HP EliteDesk 800 Tower G5 series

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration						
	http://www.epeat.net for registrati	 US ENERGY STAR® EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. 					
	*Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.						
System Configuration	The configuration used for the Ener Desktop model is based on a Typica		ared Noise Emissions data for the				
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz				
Normal Operation (Short idle)	15.02 W	14.68 W	14.94 W				
Normal Operation (Long idle)	14.34 W	13.38 W	14.12 W				
Sleep	1.20 W	1.11 W	1.25 W				
Off	0.70 W	0.72 W	0.69 W				
	model family. HP computers marke applicable U.S. Environmental Prote	ection Agency (EPA) ENERO	GY STAR® specifications for				
Heat Niccination*	applicable U.S. Environmental Prote computers. If a model family does r efficiency data listed is for a typical power supply, and a Microsoft Wind	ection Agency (EPA) ENERC not offer ENERGY STAR® co lly configured PC featuring dows® operating system.	GY STAR® specifications for ompliant configurations, then energy a hard disk drive, a high efficiency				
Heat Dissipation* Normal Operation (Short	applicable U.S. Environmental Prote computers. If a model family does r efficiency data listed is for a typical	ection Agency (EPA) ENER(not offer ENERGY STAR® co ly configured PC featuring	GY STAR® specifications for ompliant configurations, then energy				
-	applicable U.S. Environmental Prote computers. If a model family does r efficiency data listed is for a typical power supply, and a Microsoft Wind 115VAC, 60Hz	ection Agency (EPA) ENER(not offer ENERGY STAR® co ly configured PC featuring dows® operating system. 230VAC, 50Hz	GY STAR® specifications for ompliant configurations, then energy a hard disk drive, a high efficiency				
Normal Operation (Short idle) Normal Operation (Long	applicable U.S. Environmental Prote computers. If a model family does r efficiency data listed is for a typical power supply, and a Microsoft Wind 115VAC, 60Hz 51.3684 BTU/hr	ection Agency (EPA) ENERC not offer ENERGY STAR® co ly configured PC featuring dows® operating system. 230VAC, 50Hz 50.2056 BTU/hr	SY STAR® specifications for ompliant configurations, then energy a hard disk drive, a high efficiency 100VAC, 60Hz 51.0948 BTU/hr				
Normal Operation (Short idle) Normal Operation (Long idle)	applicable U.S. Environmental Prote computers. If a model family does refficiency data listed is for a typical power supply, and a Microsoft Wind 115VAC, 60Hz 51.3684 BTU/hr 49.0428 BTU/hr 4.104 BTU/hr 2.394 BTU/hr	ection Agency (EPA) ENERCY not offer ENERGY STAR® co ly configured PC featuring dows® operating system. 230VAC, 50Hz 50.2056 BTU/hr 45.7596 BTU/hr 2.4624 BTU/hr	SY STAR® specifications for ompliant configurations, then energy a hard disk drive, a high efficiency 100VAC, 60Hz 51.0948 BTU/hr 48.2904 BTU/hr 4.275 BTU/hr 2.3598 BTU/hr				
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off	applicable U.S. Environmental Prote computers. If a model family does refficiency data listed is for a typical power supply, and a Microsoft Wind 115VAC, 60Hz 51.3684 BTU/hr 49.0428 BTU/hr 4.104 BTU/hr	ection Agency (EPA) ENERCY not offer ENERGY STAR® co ly configured PC featuring dows® operating system. 230VAC, 50Hz 50.2056 BTU/hr 45.7596 BTU/hr 2.4624 BTU/hr	SY STAR® specifications for ompliant configurations, then energy a hard disk drive, a high efficiency 100VAC, 60Hz 51.0948 BTU/hr 48.2904 BTU/hr 4.275 BTU/hr 2.3598 BTU/hr				
Normal Operation (Short idle) Normal Operation (Long idle) Sleep	applicable U.S. Environmental Prote computers. If a model family does refficiency data listed is for a typical power supply, and a Microsoft Wind 115VAC, 60Hz 51.3684 BTU/hr 49.0428 BTU/hr 4.104 BTU/hr 2.394 BTU/hr NOTE: Heat dissipation is calculated	ection Agency (EPA) ENERCY not offer ENERGY STAR® co ly configured PC featuring dows® operating system. 230VAC, 50Hz 50.2056 BTU/hr 45.7596 BTU/hr 2.4624 BTU/hr	SY STAR® specifications for ompliant configurations, then energy a hard disk drive, a high efficiency 100VAC, 60Hz 51.0948 BTU/hr 48.2904 BTU/hr 4.275 BTU/hr 2.3598 BTU/hr				
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle	applicable U.S. Environmental Prote computers. If a model family does refficiency data listed is for a typical power supply, and a Microsoft Wind 115VAC, 60Hz 51.3684 BTU/hr 49.0428 BTU/hr 4.104 BTU/hr 2.394 BTU/hr NOTE: Heat dissipation is calculated attained for one hour.	ection Agency (EPA) ENERG not offer ENERGY STAR® co ly configured PC featuring dows® operating system. 230VAC, 50Hz 50.2056 BTU/hr 45.7596 BTU/hr 3.7962 BTU/hr 2.4624 BTU/hr	SY STAR® specifications for ompliant configurations, then energy a hard disk drive, a high efficiency 100VAC, 60Hz 51.0948 BTU/hr 48.2904 BTU/hr 4.275 BTU/hr 2.3598 BTU/hr vatts, assuming the service level is Sound Pressure				
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	applicable U.S. Environmental Prote computers. If a model family does refficiency data listed is for a typical power supply, and a Microsoft Wind 115VAC, 60Hz 51.3684 BTU/hr 49.0428 BTU/hr 4.104 BTU/hr 2.394 BTU/hr NOTE: Heat dissipation is calculated attained for one hour. Sound Power (LwAd, bels)	ection Agency (EPA) ENERG not offer ENERGY STAR® co ly configured PC featuring dows® operating system. 230VAC, 50Hz 50.2056 BTU/hr 45.7596 BTU/hr 3.7962 BTU/hr 2.4624 BTU/hr	TOVAC, 60Hz 100VAC, 60Hz 51.0948 BTU/hr 48.2904 BTU/hr 4.275 BTU/hr 2.3598 BTU/hr vatts, assuming the service level is Sound Pressure (LpAm, decibels)				
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle	applicable U.S. Environmental Prote computers. If a model family does refficiency data listed is for a typical power supply, and a Microsoft Wind 115VAC, 60Hz 51.3684 BTU/hr 49.0428 BTU/hr 4.104 BTU/hr 2.394 BTU/hr NOTE: Heat dissipation is calculated attained for one hour. Sound Power (LwAd, bels) 3.2 3.6 This product can be upgraded, poss features and/or components contain	ection Agency (EPA) ENERGY of the offer ENERGY STAR® colly configured PC featuring dows® operating system. 230VAC, 50Hz 50.2056 BTU/hr 45.7596 BTU/hr 3.7962 BTU/hr 2.4624 BTU/hr d based on the measured when the measured when the product may income and the control of the	TOOVAC, 60Hz 100VAC, 60Hz 51.0948 BTU/hr 48.2904 BTU/hr 4.275 BTU/hr 2.3598 BTU/hr vatts, assuming the service level is Sound Pressure (L _{pAm} , decibels) 23 26 fe by several years. Upgradeable clude:				
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk–Random writes Longevity and Upgrading	applicable U.S. Environmental Prote computers. If a model family does refficiency data listed is for a typical power supply, and a Microsoft Wind 115VAC, 60Hz 51.3684 BTU/hr 49.0428 BTU/hr 4.104 BTU/hr 2.394 BTU/hr NOTE: Heat dissipation is calculated attained for one hour. Sound Power (Lwad, bels) 3.2 3.6 This product can be upgraded, poss features and/or components contain Spare parts are available throughout production.	ection Agency (EPA) ENERGY of the offer ENERGY STAR® colly configured PC featuring dows® operating system. 230VAC, 50Hz 50.2056 BTU/hr 45.7596 BTU/hr 3.7962 BTU/hr 2.4624 BTU/hr d based on the measured when the measured when the product may income the control of the cont	TOOVAC, 60Hz 100VAC, 60Hz 51.0948 BTU/hr 48.2904 BTU/hr 4.275 BTU/hr 2.3598 BTU/hr vatts, assuming the service level is Sound Pressure (L _{pAm} , decibels) 23 26 fe by several years. Upgradeable clude: I or for up to "5" years after the end of				
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk–Random writes	applicable U.S. Environmental Prote computers. If a model family does refficiency data listed is for a typical power supply, and a Microsoft Wind 115VAC, 60Hz 51.3684 BTU/hr 49.0428 BTU/hr 4.104 BTU/hr 2.394 BTU/hr NOTE: Heat dissipation is calculated attained for one hour. Sound Power (Lwad, bels) 3.2 3.6 This product can be upgraded, poss features and/or components contains.	ection Agency (EPA) ENERGY of the offer ENERGY STAR® colly configured PC featuring dows® operating system. 230VAC, 50Hz 50.2056 BTU/hr 45.7596 BTU/hr 3.7962 BTU/hr 2.4624 BTU/hr d based on the measured when the measured when the product may income the control of the cont	TOOVAC, 60Hz 100VAC, 60Hz 51.0948 BTU/hr 48.2904 BTU/hr 4.275 BTU/hr 2.3598 BTU/hr vatts, assuming the service level is Sound Pressure (L _{pAm} , decibels) 23 26 fe by several years. Upgradeable clude: I or for up to "5" years after the end of				





	Battery size:	CR2032 (coin cell)			
	Battery type: Lithium				
Additional Information	This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -				
	2011/65/EC.				
	• This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE)				
	Directive – 20				
		t is in compliance with California Proposition 65 (S	State of California: Safe Drinking		
		oxic Enforcement Act of 1986).	, , , , , , , , , , , , , , , , , , ,		
		t EPEAT® 2019 registered where applicable. EPEA	T ® registration varies by country.		
		eat.net for registration status by country. Search k			
		for solar generator accessories at http://www.hp.			
		ts weighing over 25 grams used in the product are			
		t contains 0% post-consumer recycled plastic (by			
		t is 95.1% recycle-able when properly disposed of			
	*Based on US	EPEAT® registration according to IEEE 1680.1-2018 EPE	AT®. Status varies by country. Visit		
	http://www.	epeat.net for more information.			
Packaging Materials	External:	PAPER/Corrugated	1170 g		
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	378 g		
		PLASTIC/Polyethylene low density	17 g		
Material Usage	This product	does not contain any of the following substances	in excess of regulatory limits (refer		
	to the HP Gei	neral Specification for the Environment at			
		hp.com/hpinfo/globalcitizenship/environment/pd	f/gse.pdf):		
	 Asbestos 				
	• Certain Azo	Colorants			
	• Certain Bro	minated Flame Retardants – may not be used as fl	ame retardants in plastics		
	 Cadmium 				
		l Hydrocarbons			
	 Chlorinated 				
	Formaldehy				
		d Diphenyl Methanes			
		nates and sulfates			
		ead compounds			
		ride Batteries			
		ishes must not be used on the external surface des	signed to be frequently handled or		
	carried by the				
		eting Substances			
		nated Biphenyls (PBBs)			
		nated Biphenyl Ethers (PBBEs)			
		nated Biphenyl Oxides (PBBOs)			
		ated Biphenyl (PCB)			
	-	ated Terphenyls (PCT)			
		hloride (PVC) – except for wires and cables, and ce	rtain retail packaging has been		
		emoved from most applications.			
	Radioactive				
	• Tributyl Tin	(TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBT	0)		



Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:					
	Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging					
	materials.					
	Eliminate the use of ozone-depleting substances (ODS) in packaging materials.					
	Design packaging materials for ease of disassembly.					
	Maximize the use of post-consumer recycled content materials in packaging materials.					
	• Use readily recyclable packaging materials such as paper and corrugated materials.					
	Reduce size and weight of packages to improve transportation fuel efficiency.					
	• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.					
	UBL					
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To					
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible					
	manner.					
	mumer.					
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for					
	each product type for use by treatment facilities. This information (product disassembly					
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These					
	instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM					
	customers who integrate and re-sell HP equipment.					
	Global Citizenship Report					
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications					
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html					
	ISO 14001 certificates:					
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K					
	_Certificate.pdf					
	and					
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf					

HP FliteOne 800 G5 23.8-in All-in-One

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. *Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.			
System Configuration	The configuration used for the En Desktop model is based on a Typi	ergy Consumption and Declared No	red Noise Emissions data for the	
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	31.86	31.868	31.626	
Normal Operation (Long idle)	14.466	14.483	14.389	

Sleep	4.04	9	4.082		3.971
Off	0.64		0.64		0.623
	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.				
Heat Dissipation*	115VAC,	60Hz	230VAC,	50Hz	100VAC, 50Hz
Normal Operation (Short idle)	108.64	126	108.66	599	107.8447
Normal Operation (Long idle)	49.32	91	49.38	37	49.0665
Sleep	13.80		13.91		13.5411
Off	2.19		2.213		2.1244
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.				
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)			Sound Pressure (L _{pAm} , decibels)	
Typically Configured – Idle		2.9			21.0
Fixed Disk – Random writes		3.7			22.8
Batteries	processor. Spare parts are available throughout the warranty period and or for up to "5" years after the end of production. This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight				
	Battery size: CR2032 (coin cell) Battery type: Lithium				
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard, see http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product contains 0% post-consumer recycled plastic (by wt.) This product is 95.1% recycle-able when properly disposed of at end of life. 				
Packaging Materials		PER/Corrugated			
			anded Polyethylene)		
	PLASTIC/Polyethylene low density				
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants				



	Certain Brominated Flame Retardants – may not be used as flame retardants in plastics				
	• Cadmium				
	Chlorinated Hydrocarbons				
	Chlorinated Paraffins				
	• Formaldehyde				
	Halogenated Diphenyl Methanes				
	Lead carbonates and sulfates				
	• Lead and Lead compounds				
	Mercuric Oxide Batteries				
	Nickel – finishes must not be used on the external surface designed to be frequently handled or				
	carried by the user.				
	Ozone Depleting Substances				
	Polybrominated Biphenyls (PBBs)				
	Polybrominated Biphenyl Ethers (PBBEs)				
	Polybrominated Biphenyl Oxides (PBBOs)				
	Polychlorinated Biphenyl (PCB) Polychlorinated Biphenyl (PCB)				
	Polychlorinated Terphenyls (PCT) Polychlorida (PMS) Polychl				
	• Polyvinyl Chloride (PVC) — except for wires and cables, and certain retail packaging has been				
	voluntarily removed from most applications. • Radioactive Substances				
Dackaging Usage	• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)				
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:				
	Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging				
	materials.				
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.				
	Design packaging materials for ease of disassembly.				
	Maximize the use of post-consumer recycled content materials in packaging materials.				
	Use readily recyclable packaging materials such as paper and corrugated materials.				
	Reduce size and weight of packages to improve transportation fuel efficiency.				
	Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.				
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To				
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest				
	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible				
	manner.				
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for				
	each product type for use by treatment facilities. This information (product disassembly				
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These				
	instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM				
	customers who integrate and re-sell HP equipment.				
	Global Citizenship Report				
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html				
	Eco-label certifications				
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html				
	ISO 14001 certificates:				
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K				
	_Certificate.pdf				
	and				
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf				



Eco-Label Certifications &		in the process of l	noing cortified to	the following approvals and may		
declarations	tifications & This product has received or is in the process of being certified to the following approvals and be labeled with one or more of these marks:					
uectarations		tilese illaiks.				
	• IT ECO declaration • US ENERGY STAR®					
		ro applicable EDE	AT ® rogistration	uarios bu sountru. Coo		
	• EPEAT® 2019 registered whe					
	http://www.epeat.net for registration status by country. Search keyword generator on HP's 31 party option store for solar generator accessories at http://www.hp.com/go/options.					
	party option store for solar ger	ierator accessorie	'S at Http://www.i	iip.com/go/options.		
	*Based on US EPEAT® registration	according to IEEE 1	600 1 2010 EDEAT	® Status varios by country Visit		
	http://www.epeat.net for more		000.1-2010 EPEAT	Status varies by Country. Visit		
	http://www.epeat.net for more	illioilliation.				
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the					
Jystem comiguration	Notebook model is based on a			Noise Emissions data for the		
Energy Consumption		,, , <u>, , , , , , , , , , , , , , , , ,</u>				
(in accordance with US	447446 604	2201146		400046 600		
ENERGY STAR® test	115VAC, 60Hz	230VAC	, 50HZ	100VAC, 60Hz		
method)						
Normal Operation	12.270	12.5	1.4	12.115		
(Short idle)	13.279	13.5	14	13.115		
Normal Operation	12.116	12.2	7.5	12,000		
(Long idle)	13.116	13.275		12.889		
Sleep	0.753	0.817		0.751		
Off	0.69	0.74	46	0.689		
	NOTE: Energy efficiency data li	sted is for an ENE	RGY STAR® comp	liant product if offered within the		
	model family. HP computers m					
	applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for					
	computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy					
	efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency					
	power supply, and a Microsoft					
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz		100VAC, 60Hz		
Normal Operation	45.2814	46.0827		44.7222		
(Short idle)	73.2017	40.0627		77.7222		
Normal Operation	44.7256	45.26	570	43.9515		
(Long idle)	44.7230	45.2678		43.9313		
Sleep	2.5677	2.7860		2.5609		
Off	2.3529	2.54		2.3495		
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is					
	attained for one hour.					
Declared Noise Emissions	Sound Power	er		Sound Pressure		
(in accordance with	(L _{WAd} , bels)	(L _{WAd} , bels)		(L _{pAm} , decibels)		
ISO 7779 and ISO 9296)						
Typically Configured — Idle						
Fixed Disk – Random writes						
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable					
	features and/or components contained in the product may include:					
	Spare parts are available throu	ighout the warran	ty period and or f	or up to "5" years after the end of		
	production.					
Batteries	This battery(s) in this product o	omply with EU Dir	rective 2006/66/E	EC		
	Batteries used in the product do not contain:					
	Mercury greater the1ppm by weight					
	Cadmium greater than 20ppm by weight					
<u></u>						





Features

	Battery size:	CR2032 (coin cell)		
	Battery type			
Additional Information	This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -			
	2011/65/EC			
		oduct is designed to comply with the Waste Ele	ctrical and Electronic Equipment (WEEE)	
	Directive – 2			
		ct is in compliance with California Proposition 6	55 (State of California; Safe Drinking	
		oxic Enforcement Act of 1986).		
		ct is in compliance with the IEEE 1680 (EPEAT)		
		status by country. Search keyword generator of cessories at http://www.hp.com/go/options	on HP S 3rd party option Store for Solar	
		rts weighing over 25 grams used in the produc	t are marked per ISO11/169 and ISO10/13	
		ct contains 0% post-consumer recycled plastic		
		ct is 95.1% recycle-able when properly dispose		
Packaging Materials	External:	PAPER/Corrugated	322 g	
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	32 g	
		PLASTIC/Polyethylene low density	5 q	
Material Usage	This product	does not contain any of the following substan		
		neral Specification for the Environment at		
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/qse.pdf):			
	• Asbestos			
	Certain Azo Colorants			
	Certain Brominated Flame Retardants – may not be used as flame retardants in plastics			
	• Cadmium			
	Chlorinated Hydrocarbons			
	Chlorinated Paraffins			
	• Formaldehyde			
	Halogenated Diphenyl Methanes Lead carbonates and sulfates			
	Lead and Lead compounds			
	Mercuric Oxide Batteries			
	Nickel – finishes must not be used on the external surface designed to be frequently handled or			
	carried by the user.			
	Ozone Depleting Substances			
	Polybrominated Biphenyls (PBBs)			
	Polybrominated Biphenyl Ethers (PBBEs)			
	Polybrominated Biphenyl Oxides (PBBOs)			
	Polychlorinated Biphenyl (PCB)			
	Polychlorinated Terphenyls (PCT)			
	Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been			
	voluntarily removed from most applications.			
	 Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) 			
Packaging Usage				
rackaging osage		hese guidelines to decrease the environmental		
	Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.			
	materials.			
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.			
	Design packaging materials for ease of disassembly.			
	Maximize the use of post-consumer recycled content materials in packaging materials.			
	Use readily recyclable packaging materials such as paper and corrugated materials.			
	Reduce size and weight of packages to improve transportation fuel efficiency.			
	Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.			



Features

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Features

SERVICE AND SUPPORT

HP EliteDesk 800 G5 Tower Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

- 15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

 17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

HP EliteDesk 800 G5 Small Form Factor Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

- 15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

 17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Features

HP EliteDesk 800 G5 Desktop Mini Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

- 15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

 17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

HP EliteOne 800 G5 All-in-One Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

- 15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

 17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

CERTIFICATION AND COMPLIANCE

Energy Efficiency Compliance

ENERGY STAR® certified; EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country 19

19. *Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.



Technical Specifications – Processors

PROCESSORS

Intel® 8th and 9th Generation Core™ Processors

All HP EliteDesk 800 G5 Business PC models featuring this technology include processors that are part of the Intel® Stable Image Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP EliteDesk and EliteOne 800 G5 Business PC.

Intel® Advanced Management Technology (AMT) v12 – An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 12 includes the following advanced management functions:

- Support for configuration of Intel AMT 12.0 new capabilities
- No reset after provisioning
- Support changes to BIOS table 130
- Support for Microsoft Windows Server 2012 R2
- Support for New Microsoft SQL Server Versions including Standard and Enterprise editions
- Support for Intel SSD Prop 2500 Series
- Support for Intel Enterprise Digital Fence
- The Platform Discovery Utility can now discover these additional Intel products:
- Intel SSD Pro 2500 Series; Enterprise Digital Fence
- Intel Identity Protection Technology with One Time Password; Public Key Infrastructure; Multi Factor Authentication
- Intel Identity Protection Technology with Intel WiGig
- New Profile Editor and Profile Editor Plugin Interface
- New Required Permissions for Solutions Framework





Technical Specifications – Display Panel Specifications

DISPLAY PANEL SPECIFICATIONS

23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch or optional touch Projected Capacitive Touch supports up to 10 touch-points

Type IPS WLED Backlit LCD Active area (mm) 527.04 x 296.46 Native Resolution (HxV) 1920 x 1080

Refresh Rate 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.2745 x 0.2745

Contrast ratio (typical) 1000:1

Brightness (typical) 250nits

Viewing angle (typical) (HxV) 178 ° x 178 °

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with the use of FRC technology

Color gamut (typical) NTSC 72% Anti-glare Yes*

Response Time 14ms (Typical)

Default color temperature Warm (6500K)

23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) with HP Sure View (optional)

Type IPS WLED Backlit LCD
Active area (mm) 527.04 x 296.46
Native Resolution (HxV) 1920 x 1080

Refresh Rate 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.2745 x 0.2745

Contrast ratio (typical) 1000:1

Brightness (typical) 285 nits (non-Privacy); 400 nits (Privacy) **Viewing angle (typical) (HxV)** 178° x 178° (non-Privacy); 80° x 178° (Privacy)

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with the use of FRC technology

Color gamut (typical) NTSC 72% Anti-glare Yes*

Response Time 14ms (Typical) **Default color temperature** Warm (6500K)

2. For All in One only

Intel® HD Graphics (integrated)



^{1.} All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Technical Specifications – Display Panel Specifications

Adjustable Height Stand:	Height - Vertical/Landscape Adjustment	101mm (±2 mm)	
	Portrait Adjustment	54mm (±2 mm)	
	Tilt Angle	-5° to +20° (±3°) in landscape and portrait	
	Rotation (Swivel)	90° (±1°)	
	Pivot	Clockwise 90°	
Recline Stand:	Height - Vertical Adjustment	178 mm (±2 mm)	
	Tilt Angle	-5° to +65° (+/-3°)	
	Rotation (swivel)	360° swivel	



Technical Specifications – Graphics

GRAPHICS

HP EliteDesk 800 G5 Desktop Mini Business PC

Intel® HD Graphics (integrated)

VGA Controller Integrated

Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-

DisplayPort™ 1.2 Stream Technology for a maximum of 3 displays connected to any output controlled by Intel®

Graphics

Supports HDMI 2.0a features

HDMI (optional) Supports HDCP 2.2

Supports audio over HDMI

VGA (optional) VGA output

USB-C™ DP Alt Mode (optional) DisplayPort over the optional USB-C™ module

The actual amount of maximum graphics memory can be >4GB. System memory is allocated

Memory for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

Maximum Color Depth up to 10 bits/color

HEVC 10b Enc/Dec HW

VP9 10b Dec HW

Graphics/Video API Support HDR

Rec. 2020

DX12

 Max. Resolution (VGA)
 2048 x 1536@60Hz

 Max. Resolution (HDMI)
 4096 x 2160@60Hz

 Max. Resolution (DP)
 4096 x 2160@60Hz

AMD® Radeon™ RX 560X

Architecture Discrete GPU

AMD® GPU drives the integrated panel and all of the graphics output ports

DisplayPort Multimode capable; supports HDCP, HDR, Display Port Audio (6 streams max), DisplayPort HBR3

link rates and Multi-Stream Technology for a maximum of 5 displays (including the integrated

panel and all attached displays)

HDMI Supports HDMI 2.0b features

Supports HDCP 2.2, HDR

Memory 4GByte, 128bit wide GDDR5

Maximum Color Depth up to 12 bits/color

Graphics/Video API Support DirectX 12

OpenCL 2.0 OpenGL 4.5

AMD® Unified Video Decoder (UVD)

Rear I/O connector 1 DP

 Max. Resolution (VGA)
 2048 x 1536@60Hz

 Max. Resolution (HDMI)
 4096 x 2160@60Hz

 Max. Resolution (DP)
 5120 x 2880@60Hz



Technical Specifications – Graphics

HP EliteDesk 800 G5 Tower Business PC

Intel® UHD Graphics (integrated)

VGA Controller Integrated

Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-DisplayPort™ 1.2 Stream Technology for a maximum of 3 displays connected to any output controlled by Intel®

Supports HDMI 2.0a features

HDMI (optional) Supports HDCP 2.2

Supports BT2020 and HDR playback (7th Gen processors only)

VGA (optional) VGA ouput

USB-C™ DP Alt Mode

(optional)

DisplayPort over the optional USB-C™ module

The actual amount of maximum graphics memory can be >4GB. System memory is allocated Memory

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

Maximum Color Depth up to 10 bits/color

HEVC 10b Enc/Dec HW

VP9 10b Dec HW

Graphics/Video API Support HDR

Rec. 2020 DX12

640x480 60 Hz640x480 67Hz

640x480 72Hz 640x480 75Hz 720x400 70Hz 800x600 60Hz 800x600 75Hz 1024x768 60Hz

1024x768 75Hz

1280x960 60Hz

34" UHD Supported **Resolutions and Refresh** Rates. Other resolutions may also work.

1280x720 60Hz 1280x1024 60Hz 1280x1024 75Hz 1440x900 60Hz 1440x900 75Hz

1680x1050 60Hz 1920x1080 60Hz

3440x1440 60Hz (Native Resolution)

3440x1440 30Hz

Max. Resolution (VGA) 2048 x 1536@60Hz Max. Resolution (HDMI) 4096 x 2160@60Hz Max. Resolution (DP) 4096 x 2160@60Hz



Technical Specifications – Graphics

NVIDIA® GeForce® GT730 2GB DP DVI PCIe x8 GFX

Engine Clock902 MHzMemory Clock1250 MHzMemory Size(width)2 GB (64-bit)Memory Type256Mx32 GDDR5

 Max. Resolution(DVI)
 2560 x 1600 x 30 bpp @ 60Hz (Dual Link)

 Max. Resolution(DP)
 4096 x 2160 x 24 bpp @ 60 Hz (DP1.2)

Multi Display Support Up to 2 displays

HDCP Compliance Yes

Rear I/O connectors(bracket) DL DVI-I + DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) 35 W

PCB form-factor with bracket 2-pin fan connector for fan sink power/speed control

NVIDIA® GeForce® RTX 2060 6 GB Graphics Card

 Engine Clock
 1680 MHz

 Memory Clock
 7000 MHz

 Memory Size(width)
 6 GB(192-bit)

 Memory Type
 256M x 32 GDDR6

 Max. Resolution(DVI)
 2560x1600@60Hz

 Max. Resolution(HDMI)
 4096x2160@60Hz

 Max. Resolution(DP)
 7680x4320@60Hz

Multi Display Support 3 displays

HDCP Compliance Yes

Rear I/O connectors(bracket) DVI+HDMI+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <170W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket

AMD® Radeon™ RX 550X 4 GB FH PCIe x16

Engine Clock 1183MHz

Memory Clock 6 Gbps

Memory Size(width) 4 GB(128-bit)

Memory Type GDDR5

 Max. Resolution(HDMI)
 4096x2160 @ 60Hz

 Max. Resolution(DP)
 5120x2880 @ 60Hz

Multi Display Support 2 displays HDCP Compliance Yes

Rear I/O connectors(bracket) HDMI, DPx2

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP (low profile) PCB with FH/LP bracket



Technical Specifications – Graphics

AMD® Radeon™ RX 580 8GB GDDR5 Graphics Card

 Engine Clock
 1266 MHz

 Memory Clock
 4000 MHz

 Memory Size(width)
 8 GB (256-bit)

 Memory Type
 256M x 32 GDDR5

 Max. Resolution(HDMI)
 4096x2160@60Hz

 Max. Resolution(DP)
 5120x3200@60Hz

Multi Display Support 4 displays

HDCP Compliance Yes

Rear I/O connectors(bracket) HDMI + DPx3

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <150W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® RTX 2080 8GB GDDR6

 Engine Clock
 1710 MHz

 Memory Clock
 7000 MHz

 Memory Size(width)
 8GB (256-bit)

 Memory Type
 256M x 32 GDDR6

 Max. Resolution(Virtual Link)
 3840 x 2160@60Hz

 Max. Resolution(HDMI)
 4096 x 2160@60Hz

 Max. Resolution(DP)
 7680 x 4320@60Hz

Multi Display Support 4 displays

HDCP Compliance Yes

Rear I/O connectors(bracket) DPx3 + HDMI + Virtual Link

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <250W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® RTX 2070 8GB GDDR6

 Engine Clock
 1620 MHz

 Memory Clock
 7000 MHz

 Memory Size(width)
 8GB (256-bit)

 Memory Type
 256M x 32 GDDR6

 Max. Resolution(Virtual Link)
 3840 x 2160@60Hz

 Max. Resolution(HDMI)
 4096 x 2160@60Hz

 Max. Resolution(DP)
 7680 x 4320@60Hz

Multi Display Support 4 displays
HDCP Compliance Yes

Rear I/O connectors(bracket) DPx2 + HDMI + DVI+Virtual Link

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <210W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket



Technical Specifications – Graphics

NVIDIA® GeForce® RTX 2070 Super 8GB Graphics Card

 Engine Clock
 1770 MHz

 Memory Clock
 7000 MHz

 Memory Size(width)
 8 GB(256-bit)

 Memory Type
 256M x 32 GDDR6

 Max. Resolution(Virtual Link)
 3840*2160@60Hz

 Max. Resolution(HDMI)
 7680x4320@60Hz

Max. Resolution(DP) 5 displays
Multi Display Support Yes

HDCP Compliance DPx3 + HDMI + Virtual Link(USB-C)

Rear I/O connectors(bracket) Active fan-sink (Active cooling with dynamic speed)

Cooling(active/passive) Total 250W (with USB-C)/215 W (GFX)

Total power consumption(W) ATX (Full height) PCB with ATX dual slot bracket

PCB form-factor with bracket 1770 MHz

NVIDIA® Quadro P620 2GB Graphics Card

Engine Clock1354 MHzMemory Clock2500 MHzMemory Size(width)2GB (128-bit)Memory Type128M x 32 GDDR5Max. Resolution(DP)5120x2880@60Hz

Multi Display Support 4 displays
HDCP Compliance Yes
Rear I/O connectors(bracket) mDPx4

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <40W

PCB form-factor with bracket LP PCB with LP bracket

NVIDIA® Quadro® P1000 4GB Graphics Card

Engine Clock 1455 MHz

Memory Clock 2500 MHz

Memory Size(width) 4 GB (128-bit)

Memory Type 256M x 32 GDDR5

Max. Resolution(HDMI) Not Available

Max. Resolution(DP) 5120x2880@60Hz

Multi Display Support 4 independent displays

HDCP Compliance Yes, HDCP 2.2 **Rear I/O connectors(bracket)** 4x mDP 1.4

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) 47W

PCB form-factor with bracket Single Slot, Low Profile



Technical Specifications – Graphics

NVIDIA® Quadro P400 2GB Graphics Card

Engine Clock1252 MHzMemory Clock2000 MHzMemory Size(width)2GB (64-bit)Memory Type256M x 32 GDDR5Max. Resolution(DP)5120x2880@60Hz

Multi Display Support 3 displays
HDCP Compliance Yes
Rear I/O connectors(bracket) mDPx3

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <30W

PCB form-factor with bracket LP PCB with LP bracket

AMD® Radeon™ R7 430 2GB VGA+DP 64bit Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)2 GB(64-bit)Memory Type256M x 32 GDDR5Max. Resolution(HDMI)2048x1536

Max. Resolution(DP) 4096x2160@60Hz

Multi Display Support 2 displays
HDCP Compliance Yes
Rear I/O connectors(bracket) VGA+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket

AMD® Radeon™ R7 430 2GB GDDR5 2DP 64 bit Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)2 GB(64-bit)Memory Type256M x 32 GDDR5Max. Resolution(DP)4096x2160@60Hz

Multi Display Support 2 displays

HDCP Compliance yes **Rear I/O connectors(bracket)** DPx2

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket



Technical Specifications – Graphics

HP EliteDesk 800 G5 Small Form Factor Business PC

Intel® HD Graphics (integrated)

Memory

VGA Controller Integrated

Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and

DisplayPort™ 1.2 Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by

Intel® Graphics

Supports HDMI 2.0a features

HDMI (optional) Supports HDCP 2.2

Supports audio over HDMI

VGA (optional) VGA Output

USB-C™ DP Alt Mode (optional) DisplayPort over the optional USB-C™ module

The actual amount of maximum graphics memory can be >4GB. System memory is allocated

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide

an optimal balance between graphics and system memory use.

Maximum Color Depth up to 10 bits/color

HEVC 10b Enc/Dec HW

VP9 10b Dec HW

Graphics/Video API Support HDR

Rec. 2020 DX12

 Max. Resolution (VGA)
 2048 x 1536@60Hz

 Max. Resolution (HDMI)
 4096 x 2160@60Hz

 Max. Resolution (DP)
 4096 x 2160@60Hz

AMD® Radeon™ R7 430 2GB VGA+DP 64bit Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)1 GB(64-bit)Memory Type256M x 32 GDDR5Max. Resolution(HDMI)2048x1536

יומא. **אפטנענוטוו(חטויוו)** 2040X 1330

Max. Resolution(DP)4096x2160@60HzMulti Display Support2 displays

HDCP Compliance Yes
Rear I/O connectors(bracket) VGA+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket

AMD® Radeon™ R7 430 2GB GDDR5 2DP 64 bit Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)1 GB(64-bit)Memory Type256M x 32 GDDR5Max. Resolution(DP)4096x2160@60Hz

Multi Display Support2 displaysHDCP ComplianceyesRear I/O connectors(bracket)DPx2

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)



Technical Specifications – Graphics

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket

NVIDIA® GeForce® GT730 2GB DP DVI PCIe x8 GFX

Engine Clock902 MHzMemory Clock1250 MHzMemory Size(width)2 GB (64-bit)Memory Type256Mx32 GDDR5

 Max. Resolution(DVI)
 2560 x 1600 x 30 bpp @ 60Hz (Dual Link)

 Max. Resolution(DP)
 4096 x 2160 x 24 bpp @ 60 Hz (DP1.2)

Multi Display Support Up to 2 displays

HDCP Compliance Yes

Rear I/O connectors(bracket) DL DVI-I + DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) 35 W

PCB form-factor with bracket 2-pin fan connector for fan sink power/speed control

AMD® Radeon™ RX550 4 GB PCIe x16

Engine Clock1183MHzMemory Clock6 GbpsMemory Size(width)4 GB(128-bit)Memory TypeGDDR5

 Max. Resolution(HDMI)
 4096x2160 @ 60Hz

 Max. Resolution(DP)
 5120x2880 @ 60Hz

Multi Display Support2 displaysHDCP ComplianceYesRear I/O connectors(bracket)HDMI, DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP (low profile) PCB with FH/LP bracket

AMD Radeon™ 520 1GB Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)1 GB (32-bit)Memory Type256M x 32 GDDR5Max. Resolution(DP)2048x1536@60Hz

Multi Display Support 2 displays
HDCP Compliance Yes
Rear I/O connectors(bracket) VGA+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket



Technical Specifications – Graphics

HP EliteOne 800 G5 23.8-in All-in-One

Intel® UHD Graphics (integrated)

VGA Controller Integrated

Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-DisplayPort™ 1.2

Stream Technology for a maximum of 3 displays (including the integrated panel and all

attached displays)

Supports HDMI 2.0a features

HDMI Supports HDCP 2.2

Supports audio over HDMI

The actual amount of maximum graphics memory can be >4GB. System memory is allocated Memory

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

up to 10 bits/color **Maximum Color Depth**

HEVC 10b Enc/Dec HW VP9 10b Dec HW

Graphics/Video API Support HDR

> Rec. 2020 DX12

Max. Resolution (VGA) 2048 x 1536@60Hz Max. Resolution (HDMI) 4096 x 2160@60Hz Max. Resolution (DP) 4096 x 2160@60Hz

AMD® Radeon™ RX 560X

Architecture Discrete GPU

AMD® GPU drives the integrated panel and all of the graphics output ports

Multimode capable; supports HDCP, HDR, Display Port Audio (6 streams max), DisplayPort HBR3 **DisplayPort**

link rates and Multi-Stream Technology for a maximum of 5 displays (including the integrated

panel and all attached displays)

HDMI Supports HDMI 2.0b features

Supports HDCP 2.2, HDR

Memory 4GByte, 128bit wide GDDR5

Maximum Color Depth up to 12 bits/color

Graphics/Video API Support DirectX 12

> OpenCL 2.0 OpenGL 4.5

AMD® Unified Video Decoder (UVD)

1 DP Rear I/O connector

Max. Resolution (VGA) 2048 x 1536@60Hz Max. Resolution (HDMI) 4096 x 2160@60Hz Max. Resolution (DP) 5120 x 2880@60Hz



Technical Specifications – Storage

STORAGE

500 GB 7200RPM 3.5in SATA HDD

Capacity500 GBRotational Speed7,200 rpmInterfaceSATA 6.0 Gb/s

Buffer Size32 MBLogical Blocks976,773,168Seek Time11 ms (Average)Height1 in/2.54 cm

Media diameter: 3.5 in/8.89 cm

Width Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7200RPM 3.5in SATA HDD

Capacity1 TBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size64 MB

 Logical Blocks
 1,953,525,168

 Seek Time
 11 ms (Average)

 Height
 1 in/2.54 cm

Media diameter: 3.5 in/8.89 cm

Width (nominal) Physical size: 4 in/10.2 cm
Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 7200RPM 3.5in SATA HDD

Capacity 2 TB

Rotational Speed 7,200 rpm
Interface SATA 6 Gb/s
Buffer Size 64 MB

 Logical Blocks
 1,953,525,168

 Seek Time
 11 ms (Average)

 Height
 1.028 in/26.11 mm

 Width (nominal)
 4.0 in/101.6 mm

Operating Temperature 41° to 131° F (5° to 55° C)



Technical Specifications – Storage

500 GB 7200RPM 2.5in SATA HDD

Capacity 500 GB

Rotational Speed 7,200 rpm

Interface SATA 6 Gb/s

Buffer Size 32 MB

Logical Blocks 976,773,168

Seek Time 12 ms (Average)

Height0.267 in/6.8 mm (nominal)Width (nominal)2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7200RPM 2.5in SATA HDD

Capacity1 TBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size32 MB

Logical Blocks 1,953,525,168 **Seek Time** 12 ms (Average)

Height0.374 in/9.5 mm (nominal)Width (nominal)2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 5400RPM 2.5in SATA HDD

Capacity 2 TB

Rotational Speed 5,400 rpm
Interface SATA 6 Gb/s
Buffer Size 128 MB

Logical Blocks 3,907,050,336 **Seek Time** 12 ms (Average)

Height0.374 in/9.5 mm (nominal)Width (nominal)2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)



Technical Specifications – Storage

500 GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD

Capacity 500 GB

Architecture Self-Encrypting (SED) Solid State Drive with SATA interface

InterfaceSATA 6 Gb/sBuffer Size32 MBLogical Blocks976,773,168Seek Time12 ms (Average)

 Height
 0.267 in/6.8 mm (nominal)

 Width
 2.75 in/70 mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD

Capacity 500 GB

Architecture Self-Encrypting (SED) Solid State Drive with SATA interface

InterfaceSATA 6 Gb/sBuffer Size32 MBLogical Blocks976,773,168Seek Time12 ms (Average)

Height0.267 in/6.8 mm (nominal)Width2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 5400RPM 2.5in SATA SSHD

Capacity500 GBRotational Speed5,400 rpm

Drive Type Solid State Hybrid Drive (SSHD) technology with NAND Flash

InterfaceSATA 6 Gb/sBuffer Size64 MBNAND Flash8 GB

Seek Time 12 ms (Average)

Height0.267 in/6.8 mm (nominal)Width2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)



Technical Specifications – Storage

1 TB 5400RPM 2.5in SATA SSHD

Capacity 1 TB

Rotational Speed 5,400 rpm

Drive Type Solid State Hybrid Drive (SSHD) technology with NAND Flash

InterfaceSATA 6 Gb/sBuffer Size64 MBNAND Flash8 GB

Seek Time 12 ms (Average)

Height0.374 in/9.5 mm (nominal)Width2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 5400RPM 2.5in SATA SSHD

Capacity 2 TB
Rotational Speed 5,400 rpm

Drive Type Solid State Hybrid Drive (SSHD) technology with NAND Flash

Interface SATA 6 Gb/s
Buffer Size 128 MB
NAND Flash 8 GB

Seek Time 12 ms (Average)

Height0.374 in/9.5 mm (nominal)Width2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128 GB 2.5in SATA Three Layer Cell SSD

Drive Weight <50g
Capacity 128 GB
Height 7mm
Length 100.45mm
Width 69.85mm

InterfaceSATA 3.0 (6Gb/s)Maximum Sequential ReadUp to 530MB/sMaximum Sequential WriteUp to 380MB/sLogical Blocks250,069,680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features DIPM: TRIM



Technical Specifications – Storage

256 GB 2.5in SATA Three Layer Cell SSD

Drive Weight <62g
Capacity 256 GB
Height 7mm
Length 100.45mm
Width 69.85mm

InterfaceSATA 3.0 (6Gb/s)Maximum Sequential ReadUp to 530MB/sMaximum Sequential WriteUp to 450MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features DIPM; TRIM

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB 2.5in SATA Three Layer Cell SSD

Drive Weight <50g
Capacity 512 GB
Height 7mm
Length 100.45mm
Width 69.85mm
Interface SATA 3.0 (60

InterfaceSATA 3.0 (6Gb/s)Maximum Sequential ReadUp to 530MB/sMaximum Sequential WriteUp to 500MB/sLogical Blocks1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features DIPM: TRIM

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB 2.5in SATA Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight <50g
Capacity 256 GB
Height 7mm
Length 100.45mm
Width 69.85mm
Interface SATA 3.0 (6

InterfaceSATA 3.0 (6Gb/s)Maximum Sequential ReadUp to 530MB/sMaximum Sequential WriteUp to 500MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features DIPM; TRIM; TCG-OPAL2.0 security





Technical Specifications – Storage

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB 2.5in SATA Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight <50g
Capacity 512 GB
Height 7mm
Length 100.45mm
Width 69.85mm

InterfaceSATA 3.0 (6Gb/s)Maximum Sequential ReadUp to 530MB/sMaximum Sequential WriteUp to 500MB/sLogical Blocks1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp] **Features** DIPM; TRIM; TCG-OPAL2.0 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB 2.5in SATA Self Encrypted Federal Information Processing Standard SSD

Drive Weight<40g</td>Capacity256 GBHeight7mmLength100.45mmWidth69.85mm

InterfaceSATA 3.0 (6Gb/s)Maximum Sequential ReadUp to 530MB/sMaximum Sequential WriteUp to 500MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features DIPM; TRIM; FIPS 140-2 security



Technical Specifications – Storage

512 GB 2.5in SATA Self Encrypted Federal Information Processing Standard SSD

Drive Weight <45g
Capacity 512 GB
Height 7mm
Length 100.45mm
Width 69.85mm

InterfaceSATA 3.0 (6Gb/s)Maximum Sequential ReadUp to 530MB/sMaximum Sequential WriteUp to 500MB/sLogical Blocks1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features DIPM; TRIM; FIPS 140-2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128 GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10a 128GB Capacity Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 1400MB/s **Maximum Sequential Write** Up to 395MB/s **Logical Blocks** 250,069,680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10q Capacity 256 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 1600MB/s **Maximum Sequential Write** Up to 780MB/s **Logical Blocks** 500.118.192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2



Technical Specifications – Storage

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10a Capacity 512 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 1600MB/s **Maximum Sequential Write** Up to 860MB/s **Logical Blocks** 1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB M.2 2280 PCIe NVMe SSD

Drive Weight < 10q Capacity 1 TB Height 2.38mm Length 80mm Width 22mm PCIE Gen3 Interface **Maximum Sequential Read** Up to 1800MB/s **Maximum Sequential Write** Up to 1800MB/s **Logical Blocks** 2,000,409,264

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q Capacity 128 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 2800MB/s **Maximum Sequential Write** Up to 600MB/s **Logical Blocks** 250.069.680



Technical Specifications – Storage

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10a 256GB Capacity Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3x4 Maximum Sequential Read Up to 2700MB/s **Maximum Sequential Write** Up to 1000MB/s **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

< 10q **Drive Weight** Capacity 512 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 2900MB/s **Maximum Sequential Write** Up to 1100MB/s 1,000,215,216 **Logical Blocks**

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight< 10g</th>Capacity1 TBHeight2.38mmLength80mmWidth22mmInterfacePCIE Gen3x4



Technical Specifications – Storage

Maximum Sequential ReadUp to 3480MB/sMaximum Sequential WriteUp to 3037MB/sLogical Blocks2,000,409,264

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight < 10q Capacity 256 GB Height 2.38mm Length 80mm Width 22mm PCIE Gen3x4 Interface **Maximum Sequential Read** Up to 2700MB/s **Maximum Sequential Write** Up to 1000MB/s **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight < 10q Capacity 512 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 2900MB/s **Maximum Sequential Write** Up to 1100MB/s Logical Blocks 1.000.215.216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security



Technical Specifications – Storage

256GB Intel® Optane™ Memory H10 with Solid State Storage

Drive Weight < 10q Capacity 256 GB Height 2.38mm Length 80mm Width 22_{mm} Interface PCIE Gen3 **Maximum Sequential Read** Up to 1450MB/s **Maximum Sequential Write** Up to 500MB/s **Logical Blocks** 500.118.192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB Intel® PCIe® NVMe™ QLC + 32 GB Intel® Optane™

Drive Weight < 10a Capacity 512 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 2400MB/s **Maximum Sequential Write** Up to 1300MB/s **Logical Blocks** 1,000,215,215

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software. Not available with eMMC Base Units. Intel® Optane™ SSD is sold separately. Intel® Optane™ SSD system acceleration does not replace or increase the DRAM in your system. Available for HP commercial desktops and notebooks and for select HP workstations and requires a SATA HDD, 7th Gen or higher Intel® Core™ processor or Intel® Xeon® processor E3-1200 V6 product family or higher, BIOS version with Intel® Optane™ supported, Windows 10 version 1703 or higher, M.2 type 2280-S1-B-M connector on a PCH Remapped PCIe Controller and Lanes in x2 or x4 configuration with B-M keys that meet NVMeTM Spec 1.1, and an Intel® Rapid Storage Technology (Intel® RST) 15.5 driver.



Technical Specifications – Storage

HP 9.5mm Slim DVD-ROM Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) Up to 0.31 lb (140q) without bezel

DVD+R/-R/+RW/ **Read Speeds**

> -RW/+R DL /-R DL Up to 8X DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X

Access time

(typical reads, including

settling)

Random: DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full stroke: DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

Power Source Slimline SATA DC power receptacle

> DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions

Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80% (operating - non-condensing)

Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim DVD Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 g) **Write Speeds** DVD-R DL - Up to 6X

DVD+R - Up to 8X DVD+RW - Up to 8X DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X

DVD-RW, DVD+RW - Up to 8X

Read Speeds DVD-R DL, DVD+R DL - Up to 8X

DVD+R, DVD-R - Up to 8X DVD-ROM DL, DVD-ROM - Up to 8X

CD-ROM, CD-R - Up to 24X CD-RW - Up to 24X

Access time

(typical reads, including

settling)

Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)

Source Slimline SATA DC power receptacle **Power**

> DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)



Technical Specifications – Storage

Environmental conditions (operating - non-condensing)

Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim Blu-Ray Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 128 GB QL, 100 GB TL, 50 GB DL or 25 GB standard SL **Dimensions (W x H x D)** 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.29 lb (132 g)

Write Speeds BD-R SL/DL Up to 6X

BD-R TL/QL Up to 4X BD-R Up to 6X BD-RE Up to 2X DVD-R Up to 8X DVD-RW Up to 6X DVD+R Up to 8X DVD+RW Up to 8X DVD-RW Up to 5X CD-R Up to 24X

CD-RW Up to 10X

Read Speeds

BD-ROM Up to 6X

BD-R Up to 6X

BD-RE SL/DL Up to 6X BD-RE TL Up to 4X DVD-ROM Up to 8X DVD-R Up to 8X DVD-RW Up to 8X DVD+R Up to 8X DVD+RW Up to 8X DVD+RW Up to 8X BDMV (AACS Compliant

Disc)

Up to 6x/2x (Read/Play) DVD-RAM Up to 5x DVD-Video (CSS Compliant Disc) Up to 8x/4x (Read/Play) CD-R/RW/ROM Up to 24x

CD-DA (DAE) Up to 24X/10X (Read/Play)

Access time (typical reads, including

CD-ROM: 165 ms (typical)

settling)

Full Stroke BD-ROM: 350 ms (typical), DVD-ROM: 345 ms (typical),

Random BD-ROM: 205 ms (typical), DVD-ROM: 185 ms (typical),

CD-ROM: 340 ms (typical)

Power Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC -1200 mA typical. 2000 mA maximum

Environmental conditions (operating - non-condensing)

Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)





Technical Specifications – Networking and Communications

NETWORKING AND COMMUNICATIONS

Intel® i219LM 10/100/100	00 Integrated NIC		
Connector	RJ-45		
System Interface	PCI (Intel proprietary) + SMBus		
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)		
	100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)		
	1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)		
	Auto-Negotiation (Automatic Speed Selection)		
	Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s		
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support		
	IEEE 802.1q VLAN support		
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)		
	IEEE 802.3az EEE (Energy Efficient Ethernet)		
Performance	TCP/IP/UDP Checksum Offload (configurable)		
	Protocol Offload (ARP & NS)		
	Large send offload and Giant send offload		
	Receiving Side Scaling		
	Jumbo Frame 9K		
Power consumption	Cable Disconnetion: 25mW		
	100Mbps Full Run: 450mW		
	1000bp Full Run: 1000mW		
	WoL Enable(S3/S4/S5): 50mW		
	WoL Disable(S3/S4/S5): 25mW		
Power Management	ACPI compliant – multiple power modes		
rianagement	Situation-sensitive features reduce power consumption		
	Advanced link down power saving for reducing link down power consumption		
Management Interface	Auto MDI/MDIX Crossover cable detection		
IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)		
	PXE 2.1 Remote Boot		
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))		
	Comprehensive diagnostic and configuration software suite		
	Virtual Cable Doctor for Ethernet cable status		



Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel® i210 10/100/1000 N	IIC	
Connector	RJ-45	
System Interface	PCI (Intel proprietary) + SMBus	
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)	
	100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)	
	1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)	
	Auto-Negotiation (Automatic Speed Selection)	
	Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s	
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support	
	IEEE 802.1q VLAN support	
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)	
	IEEE 802.3az EEE (Energy Efficient Ethernet)	
Performance	TCP/IP/UDP Checksum Offload (configurable)	
	Protocol Offload (ARP & NS)	
	Large send offload and Giant send offload	
	Receiving Side Scaling Jumbo Frame 9K	
Power consumption	Cable Disconnetion: 25mW	
	100Mbps Full Run: 450mW	
	1000bp Full Run: 1000mW	
	WoL Enable(S3/S4/S5): 50mW	
	WoL Disable(S3/S4/S5): 25mW	
Power Management	ACPI compliant – multiple power modes	
rianayement	Situation-sensitive features reduce power consumption	
	Advanced link down power saving for reducing link down power consumption	
Management Interface	Auto MDI/MDIX Crossover cable detection	



IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)	
	PXE 2.1 Remote Boot	
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))	
	Comprehensive diagnostic and configuration software suite	
	Virtual Cable Doctor for Ethernet cable status	
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components	

Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11d		
	IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11d		
	IEEE 802.11n IEEE 802.11ac IEEE 802.11d		
	IEEE 802.11ac IEEE 802.11ax IEEE 802.11d		
	IEEE 802.11ax IEEE 802.11d		
	IEEE 802.11d		
	IEEE 802.11e		
	IEEE 802.11h		
	IEEE 802.11i		
	IEEE 802.11k		
	IEEE 802.11r		
	IEEE 802.11v		
Interoperability	Wi-Fi certified		
Frequency Band	802.11b/g/n/ax		
	• 2.402 – 2.482 GHz		
	802.11a/n/ac/ax		
	• 4.9 – 4.95 GHz (Japan)		
	• 5.15 – 5.25 GHz		
	• 5.25 – 5.35 GHz		
	• 5.47 – 5.725 GHz		
	• 5.825 – 5.850 GHz		
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps		
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)		
	 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) 		
	• 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)		
Modulation	Direct Sequence Spread Spectrum		
	OFDMA, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security ¹	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only		
	AES-CCMP: 128 bit in hardware		
	• 802.1x authentication		
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.		
	WPA2 certification		
	• IEEE 802.11i		
	• WAPI		
Network Architecture	Ad-hoc (Peer to Peer)		
Models	Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		
Output Power ²	• 802.11b: +18.5dBm minimum		
	• 802.11g: +17.5dBm minimum		



	• 802.11a: +18.5dl	Bm minimum	
	• 802.11n HT20(2.4GHz): +15.5dBm minimum		
	• 802.11n HT40(2.4GHz): +14.5dBm minimum		
	• 802.11n HT20(50	GHz): +15.5dBm minimum	
	• 802.11n HT40(50	GHz): +14.5dBm minimum	
	• 802.11ac VHT80	5GHz): +11.5dBm minimum	
	• 802.11ac VHT16	D(5GHz): +11.5dBm minimum	
	• 802.11ax VHT16	O(5GHz): +10dBm minimum	
Power Consumption	• Transmit mode2.	0 W	
	• Receive mode 1.6 W		
	• Idle mode (PSP) 180 mW (WLAN Associated)		
		(WLAN unassociated)	
	 Connected Stand 	by 10mW	
	• Radio disabled 8	mW	
Power Management	ACPI and PCI Expre	ss compliant power management	
	802.11 compliant	power saving mode	
Receiver Sensitivity ³	802.11b, 1Mbps: -	93.5dBm maximum	
	802.11b, 11Mbps:	-84dBm maximum	
	802.11a/g, 6Mbps	: -86dBm maximum	
	802.11a/g, 54Mbp	s : -72dBm maximum	
	802.11n, MCS07:-	-67dBm maximum	
	802.11n, MCS15:-	-64dBm maximum	
	802.11ac, MCS0: -84dBm maximum		
	802.11ac, MCS9 : -	59dBm maximum	
	802.11ax, MCS11(HT40): -59dBm maximum	
	802.11ax, MCS11(/HT160): -58.5dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure		
	Two embedded du	al band 2.4/5 GHz antennas are provided to the card to support WLAN	
	MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 M		
Dimensions	Type 2230: 2.3 x 2	2.0 x 30.0 mm	
Weight	Type 2230: 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (–10° to 70° C)	
-	Non-operating	-40° to 176° F (-40° to 80° C)	
Humidity	Operating	10% to 90% (non-condensing)	
•	Non-operating	5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
HP Integrated Module with Bl	uetooth® 4 0/4 1/4	1 2/5 A Wireless Technology	
		<u> </u>	
Bluetooth® Specification		4.0/4.1/4.2/5.0 Compliant	
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy : 0~79 (1 MF	Iz/CH)	
	BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps		
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps		
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) of the asymmetric (3-DH5) of the asymmetric (3-DH5).		
	864 kbps symmetri		
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum		
transmit power of +4 dBm for BR and EDR.			





Power Consumption	Peak (Tx) 330 mW	
	Peak (Rx) 230 mW	
	Selective Suspend 17 mW	
Range	Legacy Up to 33 ft (10 m)	
_	BLE Up to 99 ft (30 m)	
Bluetooth® Software Supported	Microsoft Windows Bluetooth® Software	
Link Topology		
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
	ETS 300 328, ETS 300 826	
	Low Voltage Directive IEC950	
	UL, CSA, and CE Mark	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance	
	LE Link Layer Ping	
	LE Dual Mode	
	LE Link Layer	
	LE Low Duty Cycle Directed Advertising	
	LE L2CAP Connection Oriented Channels	
	Train Nudging & Interlaced Scan	
	BT4.2 ESR08 Compliance	
	LE Secure Connection- Basic/Full	
	LE Privacy 1.2 –Link Layer Privacy	
	LE Privacy 1.2 –Extended Scanner Filter Policies	
	LE Data Packet Length Extension	
	FAX Profile (FAX)	
	Basic Imaging Profile (BIP)2	
	Headset Profile (HSP)	
	Hands Free Profile (HFP)	
	Advanced Audio Distribution Profile (A2DP)	
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components	

Wireless LAN Standards	D2.11ax 2x2, non-vPro, supporting gigabit file transfer speeds) non-vPro IEEE 802.11a		
	IEEE 802.11b		
	IEEE 802.11g		
	IEEE 802.11n		
	IEEE 802.11ac		
	IEEE 802.11ax		
	IEEE 802.11d		
	IEEE 802.11e		
	IEEE 802.11h IEEE 802.11i		
	IEEE 802.11k		
	IEEE 802.11r		
	IEEE 802.11v		
Interoperability	Wi-Fi certified		
Frequency Band	802.11b/g/n/ax		
	• 2.402 – 2.482 GHz		
	802.11a/ac/ax		
	• 4.9 – 4.95 GHz (Japan)		
	• 5.15 – 5.25 GHz		
	• 5.25 – 5.35 GHz		
	• 5.47 – 5.725 GHz		
	• 5.825 – 5.850 GHz		



Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps		
Data Rates	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)		
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)		
Modulation	Direct Sequence Spread Spectrum		
Houdtation	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security ¹	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only		
Security	AES-CCMP: 128 bit in hardware		
	• 802.1x authentication		
	WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.		
	WPA2 certification		
	• IEEE 802.11i		
	• WAPI		
Network Architecture	Ad-hoc (Peer to Peer)		
Models	Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		
Output Power ²	• 802.11b: +18.5dBm minimum		
-	• 802.11g : +17.5dBm minimum		
	• 802.11a: +18.5dBm minimum		
	• 802.11n HT20(2.4GHz): +15.5dBm minimum		
	• 802.11n HT40(2.4GHz): +14.5dBm minimum		
	• 802.11n HT20(5GHz): +15.5dBm minimum		
	• 802.11n HT40(5GHz): +14.5dBm minimum		
	• 802.11ac VHT80(5GHz) : +11.5dBm minimum		
	• 802.11ac VHT160(5GHz) : +11.5dBm minimum		
Power Consumption	• Transmit mode2.0 W		
	• Receive mode 1.6 W		
	• Idle mode (PSP) 180 mW (WLAN Associated)		
	• Idle mode 50 mW (WLAN unassociated)		
	Connected Standby 10mW Radio disabled 8 mW		
Daway Managament			
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode		
Receiver Sensitivity ³	802.11b, 1Mbps : -93.5dBm maximum		
Receiver Selisitivity	802.11b, 11Mbps : -83.5uBiti flaxiflutii		
	802.11a/g, 6Mbps : -86dBm maximum		
	802.11a/g, 54Mbps : -72dBm maximum		
	802.11n, MCS07 : -67dBm maximum		
	802.11n, MCS15 : -64dBm maximum		
	802.11ac, MCS0 : -84dBm maximum		
	802.11ac, MCS9: -59dBm maximum		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure		
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN		
	MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm		
Weight	Type 2230: 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating 14° to 158° F (–10° to 70° C)		
	Non-operating —40° to 176° F (–40° to 80° C)		
Humidity	Operating 10% to 90% (non-condensing)		
	Non-operating 5% to 95% (non-condensing)		



Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
HP Integrated Module with Blue	tooth® 4.0/4.1/4.2/	/5.0 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2/5.0 Cd	ompliant	
Frequency Band	2402 to 2480 MHz	!	
Number of Available Channels	Legacy : 0~79 (1 MHz/CH)		
	BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps		
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps		
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.		
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW		
Range	Legacy Up to 33 ft (10 m) BLE Up to 99 ft (30 m)		
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software		
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
	ETS 300 328, ETS 300 826		
	Low Voltage Directive IEC950		
Divisional Durafiles Companied	UL, CSA, and CE Ma		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 (LE Link Layer Ping		
	LE Dual Mode		
	LE Link Layer		
	LE Low Duty Cycle Directed Advertising		
	LE L2CAP Connection Oriented Channels		
	Train Nudging & Interlaced Scan		
	BT4.2 ESR08 Compliance		
	LE Secure Connection- Basic/Full		
	LE Privacy 1.2 –Link Layer Privacy		
	LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension		
	FAX Profile (FAX)		
	Basic Imaging Profile (BIP)2		
	Headset Profile (HSP)		
	Hands Free Profile (HFP)		
	Advanced Audio Distribution Profile (A2DP)		



Intel Thunder Peak 9260 80	2.11a/b/g/n/ac (2x2) WiFi and Bluetooth® 5.0 Combo vPro
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11bsd
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n
	• 2.402 – 2.482 GHz
	802.11a/n/ac
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum
	OFDMA, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ¹	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification
	• WPAZ CERTIFICATION • IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ²	802.11b: +18.5dBm minimum
output rowei	• 802.11g: +17.5dBm minimum
	• 802.11a: +18.5dBm minimum
	• 802.11n HT20(2.4GHz): +15.5dBm minimum
	• 802.11n HT40(2.4GHz): +14.5dBm minimum
	• 802.11n HT20(5GHz): +15.5dBm minimum
	• 802.11n HT40(5GHz): +14.5dBm minimum
	• 802.11ac VHT80(5GHz): +11.5dBm minimum
	• 802.11ac VHT160(5GHz): +11.5dBm minimum
Power Consumption	• Transmit mode2.0 W
	• Receive mode 1.6 W
	 Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated)
	• Idle mode (PSP) 180 mW (WLAN Associated)



Power Management	ACPI and PCI Express compliant power management	
· · · · · · · · · · · · · · · · · · ·	802.11 compliant power saving mode	
Receiver Sensitivity ³	802.11b, 1Mbps : -93.5dBm maximum	-
	802.11b, 11Mbps : -84dBm maximum	
	802.11a/g, 6Mbps : -86dBm maximum	
	802.11a/g, 54Mbps : -72dBm maximum	
	802.11n, MCS07 : -67dBm maximum	
	802.11n, MCS15 : -64dBm maximum	
	802.11ac, MCS0 : -84dBm maximum	
	802.11ac, MCS9 : -59dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure	
	The such added dual band 2.4/5 CHz automas are availed to the savet to avance till	A N I
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WL MIMO communications and Bluetooth communications	.AIN
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230: 2.8q	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating 14° to 158° F (–10° to 70° C)	
remperature	Non40° to 176° F (-40° to 80° C)	
	operating	
Humidity	Operating 10% to 90% (non-condensing)	
	Non- 5% to 95% (non-condensing)	
	operating	
Altitude	Operating 0 to 10,000 ft (3,048 m)	
	Non- 0 to 50,000 ft (15,240 m)	
	operating	
HP Integrated Module with Bluetoo	h® 4.0/4.1/4.2/5.0 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2/5.0 Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy : 0~79 (1 MHz/CH)	
	BLE : 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps	
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps	
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels.	
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-D	DH5) or
	864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maxim	num
	transmit power of +4 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW	
	Peak (Rx) 230 mW	
	Selective Suspend 17 mW	
Range	Legacy Up to 33 ft (10 m)	
	BLE Up to 99 ft (30 m)	
Bluetooth® Software Supported	Microsoft Windows Bluetooth® Software	
Link Topology		
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
	ETS 300 328, ETS 300 826	
	Low Voltage Directive IEC950	
	UL, CSA, and CE Mark	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance	
	LE Link Layer Ping	



	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 –Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel Thunder Peak 9260 802.11a/b/g/n/ac (2x2) WiFi and Bluetooth® 5.0 Combo Non vPro	
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n
-	• 2.402 – 2.482 GHz
	802.11a/ac
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ¹	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)



Roaming	IEEE 802.11 compl	liant roaming between access points
Output Power ²	• 802.11b : +18.5d	IBm minimum
	• 802.11g: +17.5d	IBm minimum
	• 802.11a: +18.5d	IBm minimum
	• 802.11n HT20(2.	4GHz): +15.5dBm minimum
	• 802.11n HT40(2.	4GHz): +14.5dBm minimum
	• 802.11n HT20(50	GHz) : +15.5dBm minimum
	• 802.11n HT40(50	GHz) : +14.5dBm minimum
	• 802.11ac VHT80	(5GHz) : +11.5dBm minimum
	• 802.11ac VHT16	O(5GHz): +11.5dBm minimum
Power Consumption	 Transmit mode2. 	.0 W
	• Receive mode 1	
		180 mW (WLAN Associated)
		/ (WLAN unassociated)
	 Connected Stand 	
	• Radio disabled 8	
Power Management	-	ess compliant power management
		power saving mode
Receiver Sensitivity ³	802.11b, 1Mbps : -93.5dBm maximum	
	•	: -84dBm maximum
		: -86dBm maximum
		s : -72dBm maximum
	802.11n, MCS07:	
	802.11n, MCS15:	
	802.11ac, MCS0:-	
_	802.11ac, MCS9 : -	
Antenna type	High efficiency ant	enna with spatial diversity, mounted in the display enclosure
		11 10 45 50
		al band 2.4/5 GHz antennas are provided to the card to support WLAN
		ions and Bluetooth communications
Form Factor	PCI-Express M.2 M	
Dimensions	Type 2230: 2.3 x 2	2.0 x 30.0 mm
Weight	Type 2230: 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating	14° to 158° F (-10° to 70° C)
	Non-operating	-40° to 176° F (-40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)

HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0 Wireless Technology		
Bluetooth® Specification	4.0/4.1/4.2/5.0 Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps	
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps	
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.	



Power Consumption	Peak (Tx) 330 mW
•	Peak (Rx) 230 mW
	Selective Suspend 17 mW
Range	Legacy Up to 33 ft (10 m)
	BLE Up to 99 ft (30 m)
Bluetooth® Software Supported	Microsoft Windows Bluetooth® Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
	ETS 300 328, ETS 300 826
	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping
	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 –Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)

Realtek RTL8822BE 802.11ac 2x2 Wi-Fi + BT4.2	
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n
	• 2.402 – 2.482 GHz
	802.11a/n/ac
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz



Data Datas	- 002 11b.1 2 5 5 11 Mbrs
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
88 - 4	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum
<u> </u>	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ¹	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification UFF 002 11:
	• IEEE 802.11i
No. 1 A diament	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ²	• 802.11b: +14dBm minimum
	• 802.11g: +12dBm minimum
	• 802.11a: +12dBm minimum
	• 802.11n HT20(2.4GHz): +12dBm minimum
	• 802.11n HT40(2.4GHz): +12dBm minimum
	• 802.11n HT20(5GHz): +10dBm minimum
	• 802.11n HT40(5GHz): +10dBm minimum
	• 802.11ac VHT80(5GHz): +10dBm minimum
Power Consumption	• Transmit mode2.0 W
	• Receive mode 1.6 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	• Idle mode 50 mW (WLAN unassociated)
	Connected Standby 10mW
	Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
5 1 6 11 11 2	802.11 compliant power saving mode
Receiver Sensitivity ³	802.11b, 1Mbps: -93.5dBm maximum
	802.11b, 11Mbps: -84dBm maximum
	802.11a/g, 6Mbps: -86dBm maximum
	802.11a/g, 54Mbps: -72dBm maximum
	802.11n, MCS07: -67dBm maximum
	802.11n, MCS15: -64dBm maximum
	802.11ac, MCS0: -84dBm maximum
Automora torre e	802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure
	T
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN
	MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm
Weight	Type 2230 : 2.8g
Operating Voltage	3.3v +/- 9%
Temperature	Operating 14° to 158° F (–10° to 70° C)
	Non-operating –40° to 176° F (–40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing)
	Non-operating 5% to 95% (non-condensing)
Altitude	Operating 0 to 10,000 ft (3,048 m)
	Non-operating 0 to 50,000 ft (15,240 m)





Bluetooth® Specification	4.0/4.1/4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Realtek 802.11a/b/g/n/ac (1x1) WiFi and Bluetooth® 4.2 Combo	
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h



	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n
	• 2.402 – 2.482 GHz
	802.11a/n/ac
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ¹	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
	• AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	• WPA2 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ²	• 802.11b : +14dBm minimum
Carpari Circ.	• 802.11g: +12dBm minimum
	• 802.11a: +12dBm minimum
	• 802.11n HT20(2.4GHz) : +12dBm minimum
	• 802.11n HT40(2.4GHz) : +12dBm minimum
	• 802.11n HT20(5GHz) : +10dBm minimum
	• 802.11n HT40(5GHz) : +10dBm minimum
	• 802.11ac VHT80(5GHz) : +10dBm minimum
Power Consumption	• Transmit mode2.0 W
i ower consumption	• Receive mode 1.6 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	• Idle mode 50 mW (WLAN unassociated)
	• Connected Standby 10mW
	Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
i ower management	802.11 compliant power saving mode
Receiver Sensitivity ³	802.11b, 1Mbps : -93.5dBm maximum
neceiver sensitivity	802.11b, 11Mbps : -84dBm maximum
	802.11a/g, 6Mbps : -84dBm maximum
	802.11a/g, 54Mbps : -72dBm maximum
	802.11n, MCS07 : -67dBm maximum
	802.11n, MCS07: -67dBiri maximum 802.11n, MCS15: -64dBm maximum
	802.11ac, MCS0 : -84dBm maximum
A	802.11ac, MCS9 : -59dBm maximum
Antenna type	High efficiency antenna.

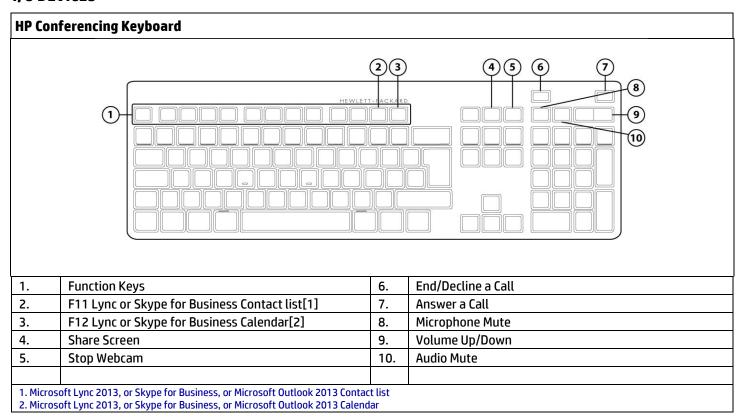


	T			
	One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN			
	communications and Bluetooth communications			
Form Factor	PCI-Express M.2 MiniCard			
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm			
Weight	Type 2230 : 2.8g			
Operating Voltage	3.3v +/- 9%			
Temperature	Operating 14° to 158° F (–10° to 70° C)			
	Non-operating	-40° to 176° F (-40° to 80° C)		
Humidity	Operating	10% to 90% (non-condensing)		
-	Non-operating	5% to 95% (non-condensing)		
Altitude	Operating 0 to 10,000 ft (3,048 m)			
	Non-operating 0 to 50,000 ft (15,240 m)			
HP Integrated Module with Blue				
Bluetooth® Specification	4.0/4.1/4.2 Compli			
Frequency Band	2402 to 2480 MHz			
Number of Available Channels	Legacy : 0~79 (1 MI	H-/CH)		
rumber of Available Chamiets	BLE: 0~39 (2 MHz/			
Data Rates and Throughput		ta rate; throughput up to 2.17 Mbps		
Data Kates and Throagnput				
		ate; throughput up to 0.2 Mbps		
		ous Connection Oriented links up to 3, 64 kbps, voice channels		
		ious Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or		
	864 kbps symmetr	ic (3-EV5)		
Transmit Power		mponent shall operate as a Class II Bluetooth® device with a maximum		
	transmit power of +4 dBm for BR and EDR.			
Power Consumption	·			
	Selective Suspend	17 mW		
Electrical Interface	USB 2.0 compliant			
Bluetooth® Software Supported	Microsoft Windows Bluetooth® Software			
Link Topology	i nerosore windows	Stateoth Software		
Power Management	Microsoft Windows ACPI, and USB Bus Support			
Certifications	ETS 300 328, ETS 3	•		
Certifications	Low Voltage Direct			
	UL, CSA, and CE Ma			
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance			
	LE Link Layer Ping			
	LE Dual Mode			
	LE Link Layer			
		Directed Advertising		
		on Oriented Channels		
	Train Nudging & Int			
	BT4.2 ESR08 Compliance			
	LE Secure Connecti			
	LE Privacy 1.2 –Linl	, ,		
	_	ended Scanner Filter Policies		
	LE Data Packet Len	gth Extension		
	FAX Profile (FAX)			
	Basic Imaging Profi			
	Headset Profile (HSP)			
	Hands Free Profile (HFP)			
	Advanced Audio Dis	stribution Profile (A2DP)		



Technical Specifications – Input/Output Devices

I/O DEVICES



Technical Specifications – Input/Output Devices

HP USB Premium Keyboar	d	
	Keys	104, 105 layout (depending upon country)
Physical Characteristics	Dimensions (L x W x H)	17.04 x 5.55 x 0.52 in (433 x 141 x13.2 mm)
	Weight	1.54 lb. (698g)
	Operating voltage	5 VDC, +/-5%
	Power consumption	35mA (All LED on)
Plantinal	System interface	USB Type A plug connector
Electrical	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
	Microsoft® PC 99 - 2001	Functionally compliant
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft. (1.8 m)
	Microsoft PC 99 - 2001	Mechanically compliant
	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
Environmental	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, FCC, CE Mark, TUV GS, VCCI	, BSMI, C-Tick, KC
Ergonomic compliance	TUVGS	
Kit contents	Keyboard, QSP	
Warranty Card	Product Notice	



Technical Specifications – Input/Output Devices

Skylab USB Wired Keyboa	rd	
	Keys	104, 105, 106, 107, 109 layout (depending upon country)
Physical Characteristics	Dimensions (L x W x H)	171.97 x 68.35 x 8.27 in (436.8± 1.5 x 137.6± 1.0 x 21.0± 1.0 cm)
	Weight	1.32 lb. (0.6± 0.08 kg)
	Operating voltage	4.4-5.25VDC
	Power consumption	50-mA maximum (with 5 VDC power supplied and three LEDs ON)
Electrical	System interface	USB
	ESD	Contact Discharge: 2, 4,6,8KV Air Discharge: 2, 4, 8,10,12.5KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
	Keycaps	Low-profile design
Mechanical	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft. (1.8 m)
	Microsoft PC 99 - 2001	Mechanically compliant
	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	Minus 30 degrees to 60 degrees Celsius
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
Environmental	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, FCC, CE Mark, TUV GS, VCCI,	BSMI, C-Tick, KC
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and	TUVGS
Kit contents	Keyboard, Installation Guide, V	Varranty card, Safety and Comfort Guide

HP USB Premium Mouse	
Dimensions (H x L x W)	4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mmm)



Technical Specifications – Input/Output Devices

Weight	0.19lb (90g)		
Environmental	Operating temperature	50° to 122°F (10° to 50° C)	
	Non-operating temperature	-22° to 140°F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	50 g, 6 surfaces	
	Non-operating shock	80 g, 6 surfaces	
	Operating vibration	2 g peak acceleration	
	Non-operating vibration	4 g peak acceleration	
Electrical	Operating voltage	5 VDC, +/-5%	
	Power consumption	12mA	
Mechanical	Connector	USB 2.0	
	Туре	3D mouse (3 keys and wheel)	
	Resolution	800, 1200, 1600 DPI	
	Sensor	Pixart PAN3606DL	
Tracking speed	Tracking acceleration	8G(max), 1G=9.8m/s2	
	Cable length	6 ft. (1.8 m)	
	Color	Jack Black	
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, C-Tick, KC	

HP USB Mouse				
Dimensions (H x L x W)	37mm x 115mm x cccc	37mm x 115mm x ccccccc62.9mm		
Weight	90 +10g/- 5 g	90 +10g/- 5 g		
Color	Black	Black		
Connector	USB	USB		
Mark and a stand	Resolution	800 DPI sensitivity		
Mechanical	Buttons	Two primary buttons and clickable scroll wheel		

Technical Specifications – Audio/Multimeda

AUDIO/MULTIMEDIA

HP EliteDesk 800 G5 Tower Business PC

Type Integrated

HD Stereo Codec Conexant CX20632

Audio I/O Ports Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-

out, Microphone-in or Headphone-out port

1 - Headphone port Rear: 1 - Line-out

1 - Line-in which is retaskable as a Microphone Input

All ports are 3.5mm and support stereo

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes

HP EliteDesk 800 G5 Small Form Factor Business PC

Type Integrated

HD Stereo Codec Conexant CX20632

Audio I/O Ports Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-

out, Microphone-in or Headphone-out port

1 - Headphone port Rear: 1 - Line-out

1 - Line-in which is retaskable as a Microphone Input

All ports are 3.5mm and support stereo

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

Playback multi-streaming can be enabled in the audio control panel to allow independent audio

Multi-streaming Capable streams to be sent to/from the front and rear jacks or integrated speaker.

Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes



Sampling

Technical Specifications – Audio/Multimeda

HP EliteDesk 800 G5 Desktop Mini Business PC

Type Integrated

HD Stereo Codec Conexant CX20632

Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-

out. Microphone-in or Headphone-out port

Audio I/O Ports 1 - Headphone port

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

Playback multi-streaming can be enabled in the audio control panel to allow independent audio

Multi-streaming Capable streams to be sent to/from the front and rear jacks or integrated speaker.

Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

Sampling to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes

HP EliteOne 800 G5 23.8-in All-in-One

Bang & Olufsen Audio

Sampling

Type Integrated

HD Stereo Codec Conexant CX5001

Side headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out,

Microphone-in or Headphone-out port

Side headphone connector supports a headphone connections

Rear line out connector

Audio I/O Ports All ports are 3.5mm and support stereo

Internal Speaker Amplifier 2W per channel class D stereo amplifier for the internal speakers only

Playback multi-streaming can be enabled in the audio control panel to allow independent audio

Multi-streaming Capable streams to be sent to/from the front and rear jacks or integrated speakers.

Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Ye

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes - Stereo



Technical Specifications – Integrated Webcam and Microphone

INTEGRATED WEBCAM AND MICROPHONE

Integrated Webcam and Microphone
Optional integrated 2 MP Full HD RGB webcam & microphone; maximum resolution of 1920 x 1080
Optional integrated 2 MP Full HD RGB dual-facing webcam with IR sensor (user-facing) & microphone; maximum resolution of 1920 x 1080

NOTE: All HP devices which carry the Bang & Olufsen brand are custom-tuned with Bang & Olufsen's acoustical engineers for precise sound experience in business use.

INTEGRATED FINGERPRINT SENSOR

Sensor type: Touch

Fingerprint matching: Performed on device

Anti-Spoofing: Yes

Windows Hello Support: Yes Encryption: On sensor FIPS Compliant: No



Technical Specifications – Power

POWER

HP EliteDesk 800 G5 Tower Business PC

Unit Environment and Operating Conditions

Operating: 5°C ~45°C

Temperature Range Non-Operating: -40°C ~66°C

Operating 5% to 90% relative humidity at max inlet temperature

Relative Humidity Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G5 SFF Business PC

Unit Environment and Operating Conditions

Operating: 5°C ~45°C

Temperature Range Non-Operating: -40°C ~66°C

Operating 5% to 90% relative humidity at max inlet temperature

Relative Humidity Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G5 Desktop Mini Business PC (35W)

Unit Environment and Operating Conditions

Operating: 5°C ~35°C

Temperature Range Non-Operating: -40°C ~66°C

Operating 5% to 90% relative humidity at max inlet temperature

Relative Humidity Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G5 Desktop Mini Business PC (65W)

Unit Environment and Operating Conditions

Operating: 5°C ~35°C

Temperature Range Non-Operating: -40°C ~66°C

Operating 5% to 90% relative humidity at max inlet temperature

Relative Humidity Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G5 Desktop Mini Business PC (95W)

Unit Environment and Operating Conditions

Operating: 5°C ~35°C

Temperature Range Non-Operating: -40°C ~66°C

Operating 5% to 90% relative humidity at max inlet temperature

Relative Humidity Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)



QuickSpecs

Technical Specifications – Power

HP EliteOne 800 G5 23.8-in All-in-One **Unit Environment and Operating Conditions**

Operating: 5°C ~45°C

Non-Operating: -40°C ~66°C **Temperature Range**

Operating 5% to 90% relative humidity at max inlet temperature

Relative Humidity Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude

(unpressurized) Non-operating: 50,000 ft. (15240 m)

	DM	SFF	TWR	AiO
External Power Supplies	65W EPS, 88% average efficiency at 115V & 89% at 230Vac 90W EPS, 88% average efficiency at 115V & 89% at 230Vac 150W EPS, 88% average efficiency at 115V & 89% at 230Vac	N/A	N/A	N/A
80 PLUS Gold	N/A	N/A	500W active PFC / 80 PLUS Gold 87/90/87% efficient at 20/50/100% load (115V)	180W active PFC / 80 PLUS Gold* 87/90/87% efficient at 20/50/100% load (115V) *Available on models with integrated graphics
80 PLUS Platinum		250W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	250W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	210W active PFC / 80 PLUS Platinum* 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V) *Available on models with discrete graphics
Operating Voltage Range	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac
Rated Line Frequency	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ
Operating Line Frequency	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ
Rated Input Current	65W≦1.6A 90W≦1.2A 150W≦2.2A	250W≦3A	500W≦6A 250W≦3A	210W≦3A 180W≦2.5A
Rated Input Current with Energy Efficient* Power Supply	65W≦1.6A 90W≦1.2A 150W≦2.2A	250W≦3A	500W≦6A 250W≦3A	210W≦3A 180W≦2.5A
DC Output	+19.5VV	+12V	+12V	+12V

DM **SFF TWR** Ai₀



Technical Specifications – Power

Current Leakage (NFPA 99:	Less than 500	Less than 500	Less than 500	Less than 500
2102)	microamps of leakage		microamps of leakage	microamps of leakage
			current at 120 Vac with	current at 120 Vac with
				the ground wire
	disconnected, as		disconnected, as	disconnected, as
		required for Non-patient		
	Electrical Appliances		Electrical Appliances	patient Electrical
	and Equipment used in a	and Equipment used in a	and Equipment used in a	Appliances and
	patient care facility or	patient care facility or	patient care facility or	Equipment used in a
	that contact patients in		that contact patients in	patient care facility or
	normal use. Per section	normal use. Per section	normal use. Per section	that contact patients in
	10.3.5.1.	10.3.5.1.	10.3.5.1.	normal use. Per section
	Less than 100		Less than 100	10.3.5.1.
	microamps of leakage		microamps of leakage	Less than 100
	current at 120 Vac with		current at 120 Vac with	microamps of leakage
	the ground wire intact		the ground wire intact	current at 120 Vac with
				the ground wire intact
		required for Non-patient		
	Electrical Appliances		Electrical Appliances	required for Non-
		and Equipment used in a		
	patient care facility or		patient care facility or	Appliances and
			that contact patients in	Equipment used in a
			normal use. Per section	patient care facility or
	10.3.5.1.	10.3.5.1.	10.3.5.1.	that contact patients in
				normal use. Per section 10.3.5.1.
Power Supply Fan	N/A	·	70mm variable speed	N/A
Power cord length	6.0 ft. (1.83 m)			
External Power Adapter	External power supply	Internal power supply	Internal power supply	Internal power supply
Dimensions	65W: 113.5mm x 55mm		500W : 165mm x	135mm x 100mm x
	x 30mm	73mm	140mm x 73mm	19.52mm
	90W: 132mm x 57mm x		250W : 165mm x 95mm	
	30mm		x 73mm	
	150W: 160mm x 80mm			
	x 40mm			
Total Cord Length	6.0 ft. (1.83 m)			

Technical Specifications – Power

The harmonic input current requirements must be met under the following operating conditions:

Load Requirements: 50% and 100%

Input Voltage: 230Vac/50Hz.

For active power factor correction the power factor at 50% &100% loads shall be greater than 0.9 over the entire nominal input voltage range (100-127VAC and 200-240VAC).

Condition	Standard Efficiency	82/85/82%	85/88/85%	87/90/87%	90/92/89%	Input Voltage
10% of Rated Load	-	75%	81%	84%	84%	115Vac/60HZ
20% of Rated Load	-	82%	85%	87%	90%	115Vac/60HZ
50% of Rated	-	85%	88%	90%	92%	115Vac/60HZ
Load	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.95	
100% of Rated	70%	82%	85%	87%	89%	115Vac/60HZ
Load	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.9	230Vac/50HZ



Technical Specifications – Weights and Dimensions

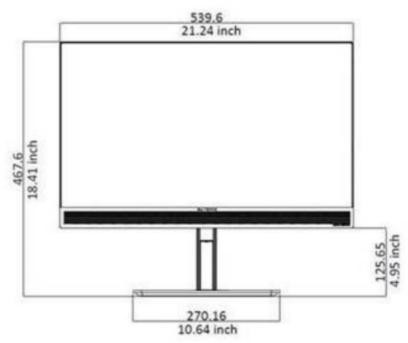
WEIGHTS & DIMENSIONS

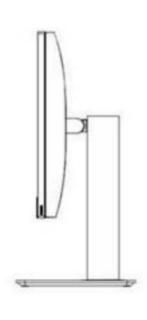
	DM	SFF	TWR	AiO
Chassis (W x D x H)	6.97 x 6.89 x 1.35 in 177x175x34mm	3.94 x 13.3 x 12.13 in 100 x 338 x 308 mm	6.1 x 14.6 x 14.4 in 154 x 370 x 365 mm	See table below.
System Volume	63.4 cu in 1.05L	63.4 cu in 10.4 L	1269 cu in 20.8 L	See table below.
System Weight	2.31 lb 1.05 kg	13.5 lb 6.13 kg	21.74 lb 9.86 kg	See table below.
Max Supported Weight (desktop orientation)	0	77 lb 35 kg	77 lb 35 kg	See table below.
Stand Dimensions	160x117x18.5mm	151.8x200x37.2mm	N/A	See table below.
Packaging (W x D x H)	19.57 x 5.04 x 8.78 in 497 x128 x223mm	15.71 x 19.65 x 9.06 in 399 x 499 x 230 mm	11.77 x 18.82 x 20.35 in 299 x 478 x 517 mm	See table below.
Shipping Weight	2.95 kg 6.49 lb	9 kg 19.82 lb	11.34 kg 24.98 lb	See table below.
Multipack Packaging (10 units)	20.28x16.54x25 in 515x420x636 mm			
Palletization Profile	18-units per layer 5 or 6 layers max depending on details of air freight 90 or 108 units per pallet depending on details of air freight 45.354 x 39.13 x 57.80 in, 1152 x 994 x 1468 mm (include pallet)	1200*1000*2438 mm (include the pallet)	8 units per layer 4 layers ax 32 units per pallet 1200*1000*2203 mm (include the pallet)	10-units per layer 4-layers max 40-units per pallet (sea) 1200 x 1000 x 2470 mm

Technical Specifications – Weights and Dimensions

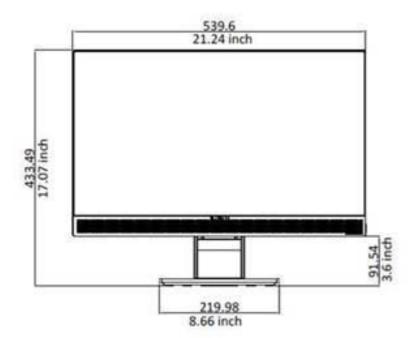
STANDS AND DIMENSIONS

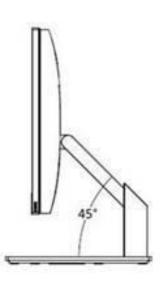
HP EliteOne G5 AIO Adjustable Height Stand





HP EliteOne G5 AIO Recline Stand





Technical Specifications – Weights and Dimensions

ALL-IN-ONE WEIGHTS AND DIMENSIONS

Weight with Touch Panel

Product Weight Unboxed	Without Stand 13.29 lbs. 6.03kg	Adjustable Height Stand 19.24 lbs. 8.73kg	Recline Stand 21.12lbs 9.58kg
Shipping Weight Boxed	Without Stand 20.64-21.15lbs 9.4-9.45kg	Adjustable Height Stand 26.68 lbs. 12.1kg	Recline Stand 28.66-28.88 lbs. 13-13.1kg
Shipping Weight Pallet	Without Stand (10units) 233.73lbs 106kg	Adjustable Height Stand (10units) 293.21lbs 133 kg	Recline Stand (10units) 313.06lbs 142kg

Weight without Touch Panel

Product Weight	Without Stand	Adjustable Height	Recline Stand
Unboxed	13.51-13.62 lbs. 6.13-6.18kg	Stand 19.46-19.68lbs	21.34-21.44 lbs. 9.68-9.73kg
	_	8.93 kg	-
Shipping Weight Boxed	Without Stand 20.86-21.06lbs 9.5-9.55kg	Adjustable Height Stand 26.89-27.12 lbs. 12.2-12.3 kg	Recline Stand 28.88lbs 13.1kg
Shipping Weight Pallet	Without Stand 21.2 x 2.12 x 13.46 in 539.6 x 53.8 x 341.79 mm	Adjustable Height Stand 0 degrees 21.2 x 7.1 x 18.4 in 539.6 x 180.28 x 467.7 mm	Recline Stand 0 degrees 21.2 x 10.3 x 10.63 in 539.6 x 261.8 x 269.98 mm

Dimensions (W x D x H)

Product	Without Stand	Adjustable Height	Recline Stand
Dimensions	21.2 x 2.12 x 13.46 in	Stand 0 degrees	0 degrees
	539.6 x 53.8 x 341.79	21.2 x 7.1 x 18.4 in	21.2 x 10.3 x 10.63 in
	mm	539.6 x 180.28 x 467.7	539.6 x 261.8 x
		mm	269.98 mm

Shipping Dimensions

Dimensions Boxed	27.17 x 10.08 x 21.46(H) in 690 x 256 x 545(H)	Stand 27.17 x 10.08 x 26.22(H) in	Recline Stand 27.17 x 10.08 x 26.22(H) in 690 x 256 x 666(H) mm
		mm	
Pallet	(10 units) 47.24 x 39.37 x 24.02(H) in 1200 x 1000 x 610(H)	Stand (10 units) 47.24 x 39.37 x 28.94(H) in 1200 x 1000 x 735(H)	Recline Stand (10 units) 47.24 x 39.37 x 28.94(H) in 1200 x 1000 x 735(H) mm



Technical Specifications – Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode.
 Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
 - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
 - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
 - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
 - 2 red + 4 white BIOS recovery is in progress
 - 3 red + 2 white Memory could not be initialized
 - 3 red + 3 white Graphics adaptor could not be found
 - 3 red + 4 white Power supply failure / not connected
 - 3 red + 5 white Processor not installed
 - 3 red + 6 white Current processor does not support an enabled feature
 - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
 - 4 red + 3 white System internal temperature has exceeded its threshold
 - 5 red + 2 white System controller firmware is not valid
 - 5 red + 3 white System controller detected BIOS is not executing
 - 5 red + 4 white BIOS could not complete initialization / PCA failure
 - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
 - This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software5 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- Clear Password Jumper
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- · System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal (For MT, SFF, and DM only)
- Green Pull Tabs, and Quick Release Latches for easy Identification



Technical Specifications – Miscellaneous Features

Additional Features	Description
Tower Orientation	Product can be oriented as either a desktop (horizontal) or a tower (vertical) for MT, SFF, and DM only
Drive Lock	Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined passwords are provided.
Boot Sectors Protection	MBR and GPT sectors of the hard drive are critical to booting the operating system. By saving the MBR or GPT data (depending on the how the OS was installed), the BIOS will be able to monitor for changes and allow the user to override them with the backup copy at boot-up.
Drive Protection System	DPS Access through F10 Setup during Boot
	A diagnostic hard drive self- test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user
	Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced
	The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures
SMART Technology (Self-Monitoring, Analysis and Reporting Technology)	Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted
SMART I - Drive Failure Prediction	Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count
SMART II - Off-Line Data Collection	By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure
SMART III - Off-Line Read Scanning with Defect Reallocation	IOEDC: I/O Error Detection Circuitry
SMART IV - End-to-End CRC for hard drives	Detects errors in Read/Write buffers on HDD cache RAM



Technical Specifications – After Market Options

AFTER MARKET OPTIONS

Graphics Solutions	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
AMD® Radeon™ RX 550X 4GB LP Display Port Card		X			5LH79AA
AMD® Radeon™ R7 430 2GB 2 Display Port Card		X	X		5JW82AA
AMD® Radeon™ R7 430 2GB Display Port VGA 64bit Card (China Only)		Х	Х		5JW81AA
NVIDIA GeForce GT730 DP 2GB PCIe x8 GFX		X	X		Z9H51AA
HP DisplayPort To HDMI True 4k Adapter	X	X	X	X	2JA63AA
HP DVI Cable Kit	X	X	X	X	DC198A
HP HDMI Standard Cable Kit	Х	X	X	X	T6F94AA
HP DisplayPort Cable Kit	Х	X	Х	X	VN567AA
HP DisplayPort To VGA Adapter	X	X	X	X	AS615AA
HP DisplayPort To DVI-D Adapter	X	X	X	X	FH973AA

Desktop Mini Accessories	<u>DM</u>	<u>SFF</u>	<u>MT</u>	<u>AiO</u>	Part Number
HP Desktop Mini G3 Port Cover Kit	Х				1ZE52AA
HP G4 Mini 2.5-inch SATA Drive Bay Kit	X				3TK91AA
HP Desktop Mini LockBox V2	X (95W and discrete GPU skus not supported)				3EJ57AA
HP Desktop Mini DVD-Writer ODD Expansion Module	X (Either one)				K9Q83AA
HP Desktop Mini I/O Expansion Module	A (Either one)				K9Q84AA
HP Desktop Mini Security/Dual VESA Sleeve v2	X (95W and discrete GPU skus not supported)				2JA32AA
HP Desktop Mini Security/Dual VESA Sleeve v2 with Power Supply Holder	X (95W and discrete GPU skus not supported)				7DB36AA
HP B300 PC Mounting Bracket	Х				2DW53AA
HP B300 PC Mounting Bracket with Power Supply Holder	Х				7DB37AA
HP B500 PC Mounting Bracket	X				2DW52AA
HP Desktop Mini Vertical Chassis Stand	X				G1K23AA
HP DM VESA Power Supply Holder Kit v2	Х				7DB38AA
HP Quick Release Bracket 2	X			X	6KD15AA
HP Single Monitor Arm	X			X	BT861AA



Technical Specifications – After Market Options

Data Storage Drives	<u>DM</u> <u>SFF</u>		TWR	<u>AiO</u>	<u>Part</u> <u>Number</u>
HP 256GB SATA TLC Non-SED Solid State Drive	X (95W and discrete GPU skus not supported, cannot use in conjunction with Thunderbolt 3 and Fiber NIC and any Fiber NIC option card)	х	x	х	P1N68AA
HP PCIe NVME TLC 256GB SSD M.2 Drive	Х	X	Х	Х	1CA51AA
HP PCIe NVME TLC 512GB SSD M.2 Drive	X	X	Х	Х	X8U75AA
HP PCIe NVME TLC 512GB SSD PCIe Drive		X	Х		Z4L70AA
HP 500GB 7200PRM SATA 6.0Gb/s 3.5" Hard Drive		х	X		QK554AA
HP 1TB 7200rpm SATA 6Gb/s 3.5" Hard Drive		х	X		QK555AA
HP 500GB SATA 6Gb/s 7200 HDD		X	Х		LQ036AA
HP 1TB SATA 6Gb/s 7200 HDD		X	Х		LQ037AA
HP 3.5" Removable SATA HDD Frame/Carrier			X		RY102AA
HP 9.5mm G3 800/600 Tower DVD-Writer (need to be confirmed)			X		1CA52AA

Input Devices	<u>DM</u>	<u>SFF</u>	TWR	<u>AiO</u>	<u>Part</u> <u>Number</u>
HP USB (Grey) SmartCard CCID Keyboard		X	X		J7H70AA
HP USB Antimicrobial Business Slim Keyboard and Mouse (China Only)		Х	X	Х	Z9H50AA
HP USB Business Slim CCID SmartCard Keyboard	X	X	X	Х	Z9H48AA
HP USB Business Slim (Grey) Keyboard (EMEA Only)	X	X	X	Х	Z9H49AA
HP USB Business Slim Keyboard	X	X	X	Х	N3R87AA
HP USB Business Slim Keyboard and Mouse and Mousepad		Х	X	X	T4E63AA
HP USB Collaboration Keyboard	X	X	X		Z9N38AA
HP USB Conferencing Keyboard				X	K8P74AA
HP USB Keyboard	X	Х	X	X	QY776AA
HP USB Keyboard and Mouse Healthcare Edition	Х	Х	X	Х	1VD81AA
HP USB Premium Keyboard	Х	Х	X	Х	Z9N40AA
HP USB PS/2 Washable Keyboard & Mouse	X	X	X	X	BU207AA
HP Wireless Business Slim Keyboard and Mouse	Х	X	X	Х	N3R88AA
HP Wireless Collaboration Keyboard	X	X	X		Z9N39AA
HP Wireless Premium Keyboard		X	X	Х	Z9N41AA
HP PS/2 Business Slim Keyboard		Х	X		N3R86AA
HP USB Grey v2 Mouse (EMEA only)	Х	Х	X	Х	Z9H74AA
HP USB Premium Mouse	X	Х	X	Х	1JR32AA
HP PS/2 Mouse		Х	X		QY775AA
HP USB 1000dpi Laser Mouse	Х	Х	Х	Х	QY778AA



Technical Specifications – After Market Options

HP USB Hardened Mouse	X	Х	Х	X	P1N77AA
HP USB Mouse	Х	Х	Х	Х	QY777AA

System Memory	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part</u> <u>Number</u>
HP 4GB DDR4-2666 DIMM		Х	X		3TK85AA
HP 8GB DDR4-2666 DIMM		Х	X		3TK87AA
HP 16GB DDR4-2666 DIMM		Х	X		3TK83AA
HP 4GB DDR4-2666 SODIMM	Х			Х	3TK86AA
HP 8GB DDR4-2666 SODIMM	Х			X	3TK88AA
HP 16GB DDR4-2666 SODIMM	X			X	3TK84AA

Multimedia Devices	<u>DM</u>	<u>SFF</u>	TWR	<u>AiO</u>	<u>Part</u> <u>Number</u>
HP Business Headset v2	X	Х	X	X	T4E61AA
HP S101 Speaker Bar	X	Х	X		5KC42AA

Security Devices	<u>DM</u>	<u>SFF</u>	TWR	<u>AiO</u>	<u>Part</u> <u>Number</u>
HP Business PC Security Lock v3 Kit		X	Х		3XJ17AA
HP 800 G3 (SFF) Solenoid Lock and Intrusion Sensor		х			1CA50AA
HP Dual Head Keyed Cable Lock		X	Х		T1A64AA
HP Keyed Cable Lock 10mm	X	Х	Х	X	T1A62AA
HP Master Keyed Cable Lock 10mm		X	Х	Х	T1A63AA

Stands and Accessories	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP ProOne G4 Height Adjustable Stand				Х	4CX34AA



Technical Specifications – After Market Options

I/O Devices	<u>DM</u>	<u>SFF</u>	TWR	<u>AiO</u>	<u>Part</u> <u>Number</u>
HP DisplayPort Port Flex IO	X (discrete GPU skus not supported)	х	х		3TK72AA
HP Fiber NIC (100Mbps) Port Flex IO	X (95W and discrete GPU skus not supported)				ЗТК7ЗАА
HP HDMI Port Flex IO (400/600/800)	X (discrete GPU skus not supported)	х	х		3TK74AA
HP Thunderbolt 3.0 Port Flex IO	X (95W and discrete GPU skus not supported)				ЗТК77АА
HP Thunderbolt 3.0 PCIe Card		X	X		4CX35AA
HP Type-C™ USB 3.1 Gen2 Port Flex IO	X (discrete GPU skus not supported)	х	х		3TK78AA
HP Type-C™ USB 3.1 Gen2 Port with PD Flex IO	X (95W and discrete GPU skus not supported)				ЗТК79АА
HP VGA Port Flex IO	X (discrete GPU skus not supported)	х	х		3TK80AA
HP Serial Port Flex IO	X (discrete GPU skus not supported)				3TK76AA
HP Internal Serial Port (600/705/800)		Х	X		3TK82AA
HP PCIe x1 Parallel Port Card		X	Х		N1M40AA

NOTE: For more detail on HP I/O Devices please refer to the HP FLEX IO Option Cards QuickSpecs. URL is: http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06042607

Communication Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part</u> <u>Number</u>
Intel® 9260 802.11ac non-vPro™ PCIe x1 Card		X	X		3TK89AA
Realtek 8822BE 802.11ac PCIe x1 Card		X	X		3TK90AA

Intel® Optane Memory	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part</u> <u>Number</u>
Intel® Optane Memory 16GB (Cache)	Х	Х	Х	Х	1WV97AA



Change Log

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Date	Version History	Action	Description of Change
July 11, 2019	From v1 to v2	Update	Environmental tables for DM/SFF updated
July 19, 2019	From v2 to v3	Update	DM rear call outs image updted
			AMO section updated
July 31, 2019	From v3 to v4	Update	Weights and dimensions table updated
			TPM description updated
			Typo in 2TB M.2 SSD description corrected
August 15, 2019	From v4 to v5	Update	NOTE added in AMO section under I/O Devices
August 20, 2019	From v5 to v6	Update	Cable lock slot upgraded to Standard
			Intel® Core™ i5 8500 made able to DM
September 17, 2019	1	Update	Note added to Graphics
September 20, 2019	From v7 to v8	Update	Intel® Wi-Fi 6 AX200 corrected
October 2, 2019	From v8 to v9	Update	RTX 2080, RTX 2070, RTX 2060 names corrected
October 8, 2019	From v9 to v10	Update	Second bullet added to At a Glance section
October 15, 2019	From v10 to v11	Update	HP ProOne 600/400 G4 VESA Plate removed from AMO
October 18, 2019	From v11 to v12	Update	AiO call outs re-arranged for back and side images, adding
			Standard lock slot
October 31, 2019	From v12 to v13	Update	EPEAT references updated / Power Factor table added to Power
			Supply / 256 GB M.2 2280 PCIe NVMe SSD added to Storage
November 20, 2019	From v13 to v14	Update	AMD Radeon 520 1GB DP/VGA added to Graphics
November 26, 2019	From v14 to v15	Update	AMD® Radeon™ RX 550X 4GB LP Display Port Card set only for
			SFF in AMO / and NVIDIA® Quadro P620 2GB Graphics Card set
			for SFF in Graphics section
January 24, 2020	From v15 to v16	Update	AMO section updated
February 3, 2020	From v16 to v17	Update	HP Fiber NIC (100Mbps) Port Flex IO- AMO Section Update
February 19, 2020	From v17 to v18	Update	Drivelock note and disclaimer added
			SFF Enviromental data corrected
February 26, 2020	From v18 to v19	Update	Processor I7-9700 specs corrected
March 3, 2020	From v19 to v20	Update	Core i5-9400, Core i5-9400T, Core i5-8400, Core i5-8400T
			processors, and "Removable" in Storage section added.
March 4, 2020	From v20 to v21	Update	NVIDIA GeForce RTX2070 Super 8GB and NVIDIA Quadro P1000
			4GB added

